Compal Confidential

Model Name: V5WE2/T2/C2 (EA/EG/BA50_HW)

File Name: LA-9531P

Compal Confidential

EA50_HW M/B Schematics Document

Intel Shark Bay ULT (Hasswell + Lynx Point-LP)

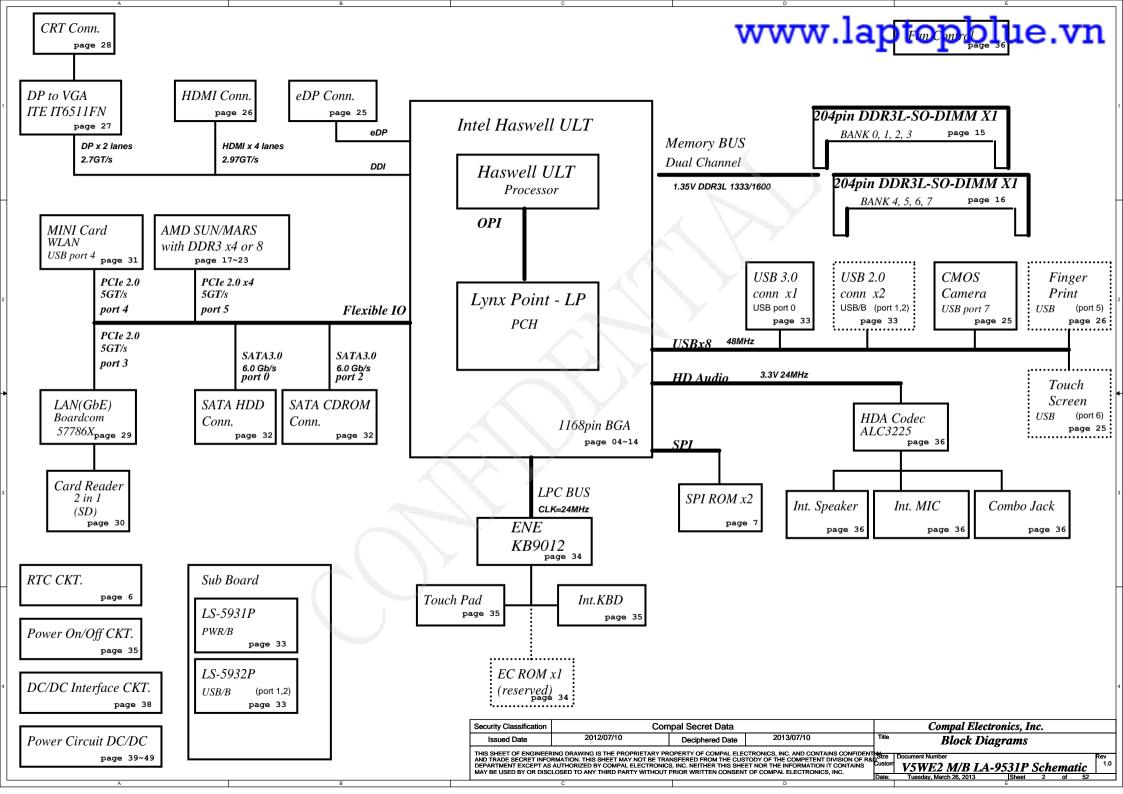
AMD MARS / SUN

2013-04-11

REV: 1.0

ZZZ	
Part Number	Description
DAZ0VR00100	PCB V5WE2 LA-9531P LS-9531P/9532P
V5WE2_PCB	

Security Classification	ion Compal Secret Data				Compal Electronics, Inc.	
Issued Date	2012/07/10	Deciphered Date	2013/07/10	Title	Cover Page	
	RING DRAWING IS THE PROPRIETARY P DRMATION. THIS SHEET MAY NOT BE TR 3 AUTHORIZED BY COMPAL ELECTRONIC CLOSED TO ANY THIRD PARTY WITHOUT		ECTRONICS, INC. AND CONTAINS CONFIDE STODY OF THE COMPETENT DIVISION OF F EET NOR THE INFORMATION IT CONTAINS IT OF COMPAL ELECTRONICS, INC.	Size Custom Date:	Document Number V5WE2 M/B LA-9531P Schematic Thursday, April 11, 2013 Sheet 1 of 52	Rev 1.0



Voltage Rails

Power Plane	Description	S1	S3	S5
VIN	Adapter power supply (19V)	N/A	N/A	N/A
BATT+	Battery power supply (12.6V)	N/A	N/A	N/A
B+	AC or battery power rail for power circuit.	N/A	N/A	N/A
+CPU_CORE	Core voltage for CPU	ON	OFF	OF
+VGA_CORE	Core voltage for GPU	ON	OFF	OF
+0.675VS	+0.675VS power rail for DDR3L terminator	ON	OFF	OFF
+1.05VS_VTT	+1.05V power rail for CPU	ON	OFF	OFF
+0.95VSDGPU	+0.95VSDGPU switched power rail for GPU	ON	OFF	OF
+1.35V	+1.35V power rail for DDR3L	ON	ON	OF
+1.5VS	+1.5V power rail for CPU	ON	OFF	OF
+1.5VSDGPU	+1.5VSDGPU power rail for GPU	ON	OFF	OF
+1.8VSDGPU	+1.8VSDGPU power rail for GPU	ON	OFF	OFI
+3VALW	+3VALW always on power rail	ON	ON	ON'
+3VLP	B+ to +3VLP power rail for suspend power	ON	ON	ON
+3VS	+3VALW to +3VS power rail	ON	OFF	OF
+3VSDGPU	+3VS to +3VSDGPU power rail for GPU	ON	OFF	OF
+5VALW	+5VALWP to +5VALW power rail	ON	ON	ON
+5VS	+3VALW to +5VS power rail	ON	OFF	OF
+RTCVCC	RTC power	ON	ON	ON
Note : ON* means	 s that this power plane is ON only with AC power availabl	e, otherwise it is	OFF.	

EC SM Bus1 address

EC SM Bus2 address

Device	Address	Device	Address
Smart Battery	0001 011X	On Board Thermal Senser	0100 110x
		VGA Internal Thermal Senser	0100 000x
		G Senser	0011 000x

PCH SM Bus address

Device		Address	
ChannelA	DIMM0	1001 000x	JDIMM1
ChannelB	DIMM1	1001 010	.IDIMM2

SIGNAL	SLP_S1#	SLP_S3#	SLP_S4#	SLP_S5#	+VALW	7 -	+VS	Clock	nhluo m
Full ON	HIGH	HIGH	HIGH	нісн	WV	•¶C	L		bpine vii
S1(Power On Suspend)	LOW	HIGH	HIGH	HIGH	ON	ON	ON	LOW	
S3 (Suspend to RAM)	LOW	LOW	HIGH	HIGH	ON	ON	OFF	OFF	
S4 (Suspend to Disk)	LOW	LOW	LOW	HIGH	ON	OFF	OFF	OFF	
S5 (Soft OFF)	LOW	LOW	LOW	LOW	ON	OFF	OFF	OFF	1

Board ID / SKU ID Table for AD channel

Vcc	3.3V +/- 5%			
Ra/Rc/Re	100K +/- 5%	A		
Board ID	Rb / Rd / Rf	Vad_BID min	Van_BID typ	Vad_bid max
0	0	0 V	0 V	0 V
1	8.2K +/- 5%	0.216 V	0.250 V	0.289 V
2	18K +/- 5%	0.436 V	0.503 V	0.538 V
3	33K +/- 5%	0.712 V	0.819 V	0.875 V
4	56K +/- 5%	1.036 V	1.185 V	1.264 V
5	100K +/- 5%	1.453 V	1.650 V	1.759 V
6	200K +/- 5%	1.935 V	2.200 V	2.341 V
7	NC	2.500 V	3.300 V	3.300 V

BOARD ID Table

Board ID	PCB Revision
0	0.1
1	0.2
2	0.3
3	0.4
4	0.5
5	1.0
6	
7	

USB Port Table

Port	3 External USB Port
0	USB Port(Left 3.0)
1	USB Port(Right 2.0)
2	USB Port(Right 2.0)
3	
4	Mini Card (WLAN+BT)
5	
6	
7	Camera
	0 1 2 3 4 5

DTO Option Table						
BTO Item	BOM Structure					
Unpop	@					
Connector	CONN@					
EC 932	940@					
EC 9012	9012@					
UMA Component	UMA@					
AMD GPU	VGA@					
1 SPI ROM	1ROM@					
2 SPI ROM	2ROM@					
Assembly Level	45@					
Cable for Power	45PWR@					
KB Backlight	BL@					
Debug Only	DEG@					
EMC Component	EMC@					
Reservec for EMC	XEMC@					
eDP to LVDS	TL@					
TPM Module	TPM@					
G-Sensor	GSEN@					
V5WE2/T2/C2	EA50@					
Reserved	BA51@					
Touch Screen	TS@					
For IOAC	IOAC@					
For EDP panel	EDP@					
Mars component	MARS@					
SUN component	SUN@					
VRAM x 8pcs	128@					
VRAM Selection	X76@					
Micron 4G x 8	X7601@					
Hynix 2G x 4	X7603@					
Hynix 2G x 8	X7604@					

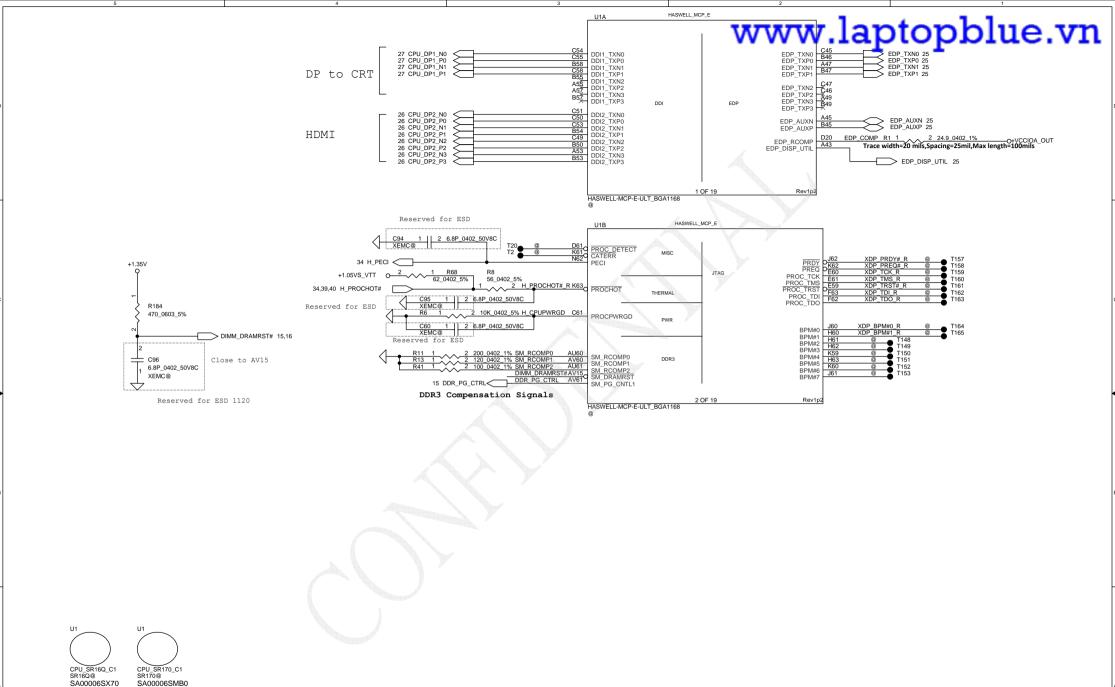
BTO Option Table

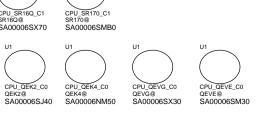
USB 3.0	Port	
	0	USB Port(Left 3.0)
XHCI	1	
Ancı	2	
	3	

Security Classification	Compal Secret Data				Compal Electronics, Inc.
Issued Date	2012/07/10	Deciphered Date	2013/07/10	Title	Notes List
THIS SHEET OF ENGINEER	RING DRAWING IS THE PROPRIETARY PI	ROPERTY OF COMPAL ELE	ECTRONICS, INC. AND CONTAINS CONFIDEN	TeNs π	Dogument Number Per

HIS SHEET OF ENGINEERING PARKWING IS THE PROPRIET PARY PROPERLY OF COMPALE LECTRONICS, INC. AND COLD TAINS CONNECTED STAR AND TRADE SCORET INFORMATION. THIS SHEET MAY NOT BE TRANSFERED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R DEPARTMENT EXCEPT AS AUTHORIZED BY COMPALE LECTRONICS, INC. NETHER FIRS SHEET NOT THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPALE LECTRONICS, INC.

V5WE2 M/B LA-9531P Schematic 1.0

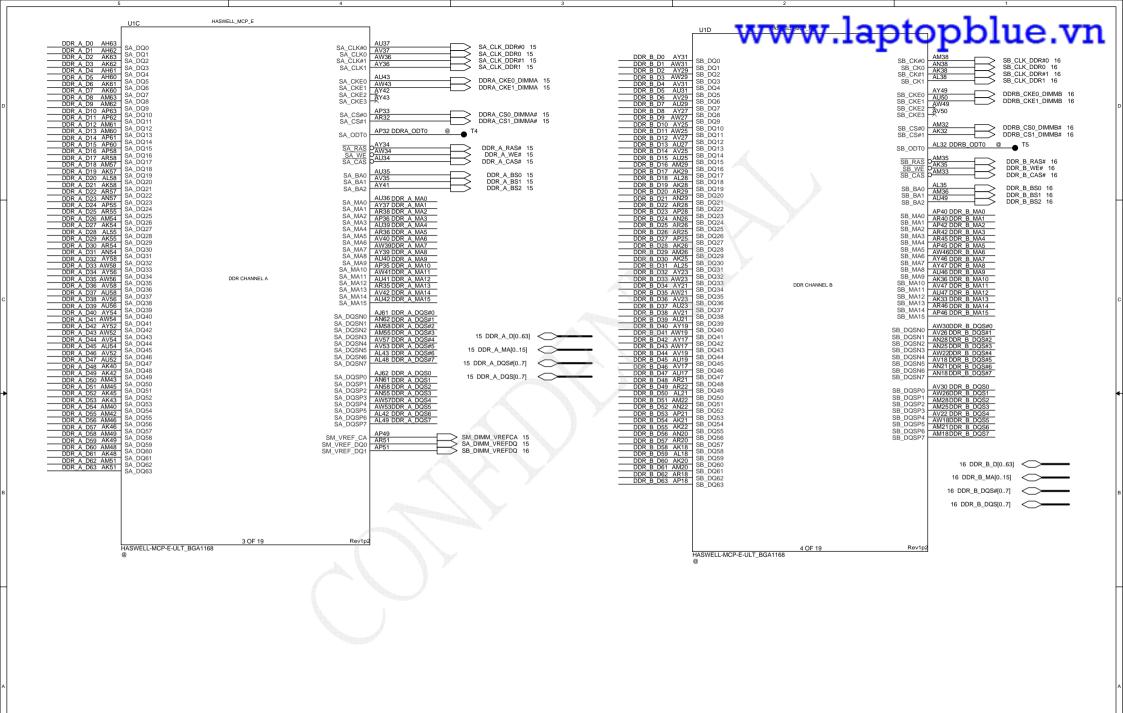




Security Classification	Con	npal Secret Data			Compal Electronics, Inc.	
Issued Date	2012/07/10	Deciphered Date	2013/07/10	Title	HSW MCP(1/11) DDI,MSIC,XDI	P
THIS SHEET OF ENGINEER AND TRADE SECRET INFOI DEPARTMENT EXCEPT AS	RING DRAWING IS THE PROPRIETARY PR RMATION. THIS SHEET MAY NOT BE TRA AUTHORIZED BY COMPAL ELECTRONIC	OPERTY OF COMPAL ELEC INSFERED FROM THE CUS S, INC. NEITHER THIS SHE	CTRONICS, INC. AND CONTAINS CONFIDENT TODY OF THE COMPETENT DIVISION OF R& ET NOR THE INFORMATION IT CONTAINS	Size Custom		ev 1.0

MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS. INC.

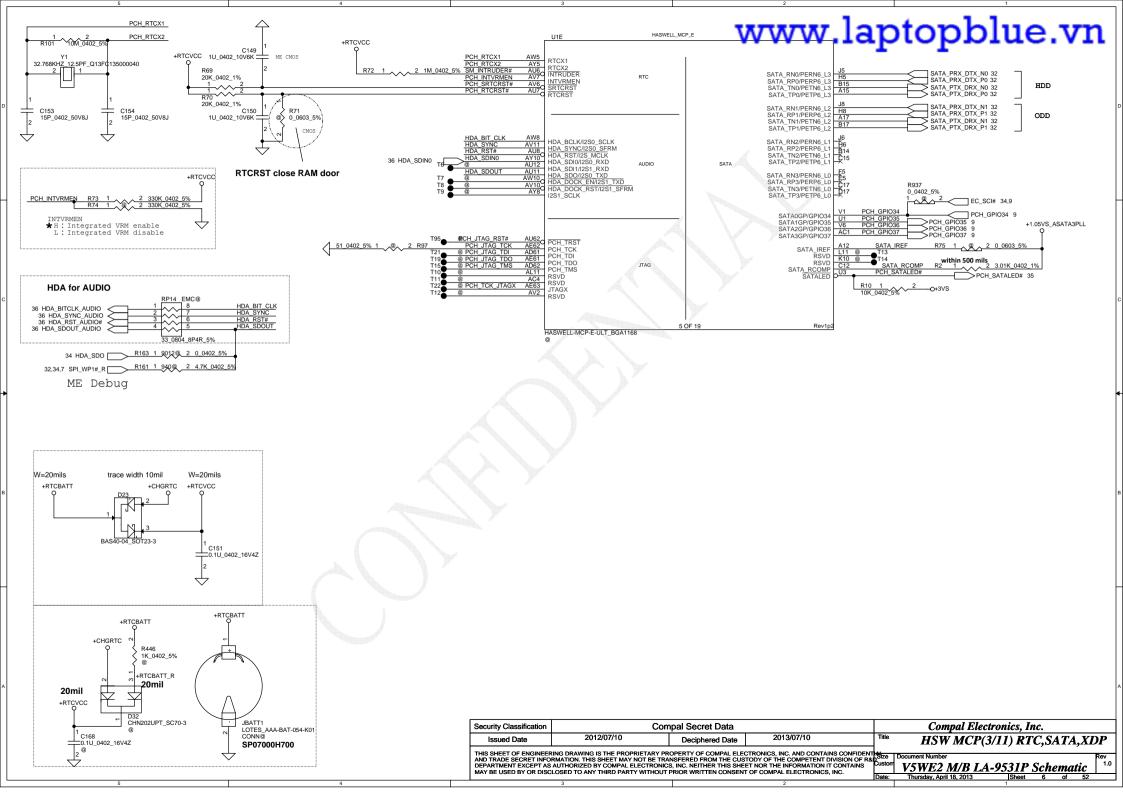
V5WE2 M/B LA-9531P Schematic Date: Monday, April 08, 2013 Sheet 4 of

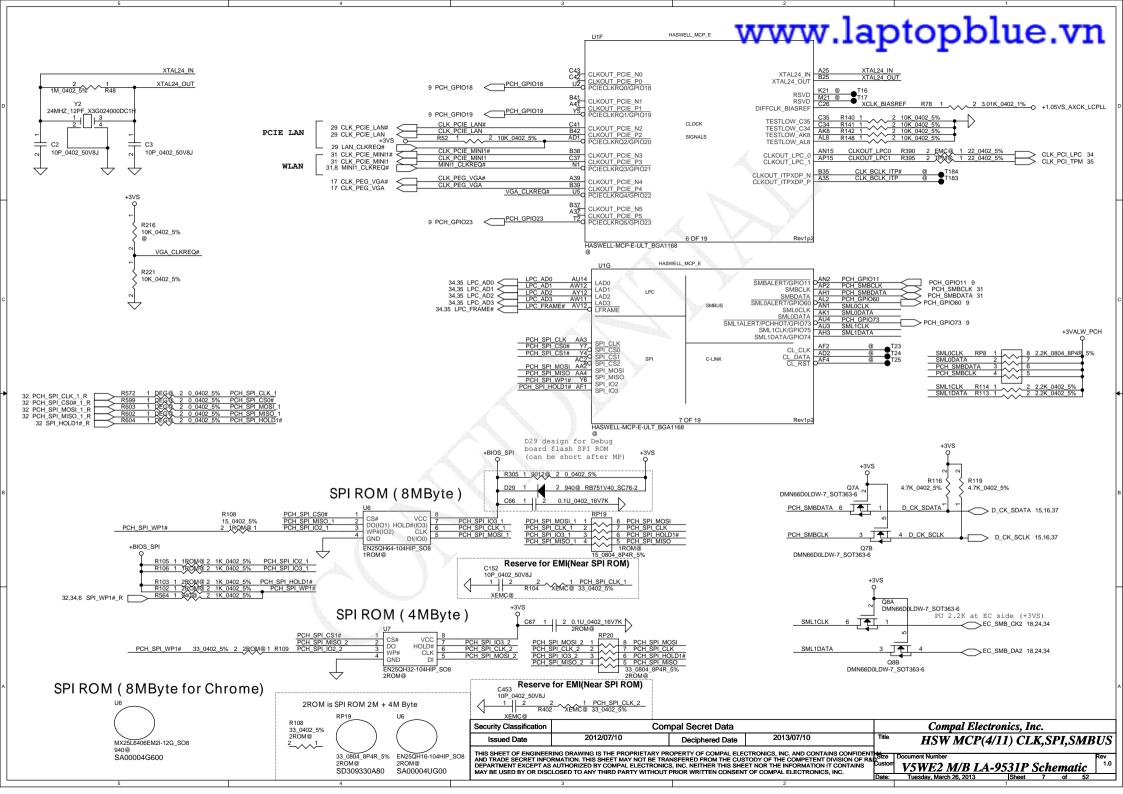


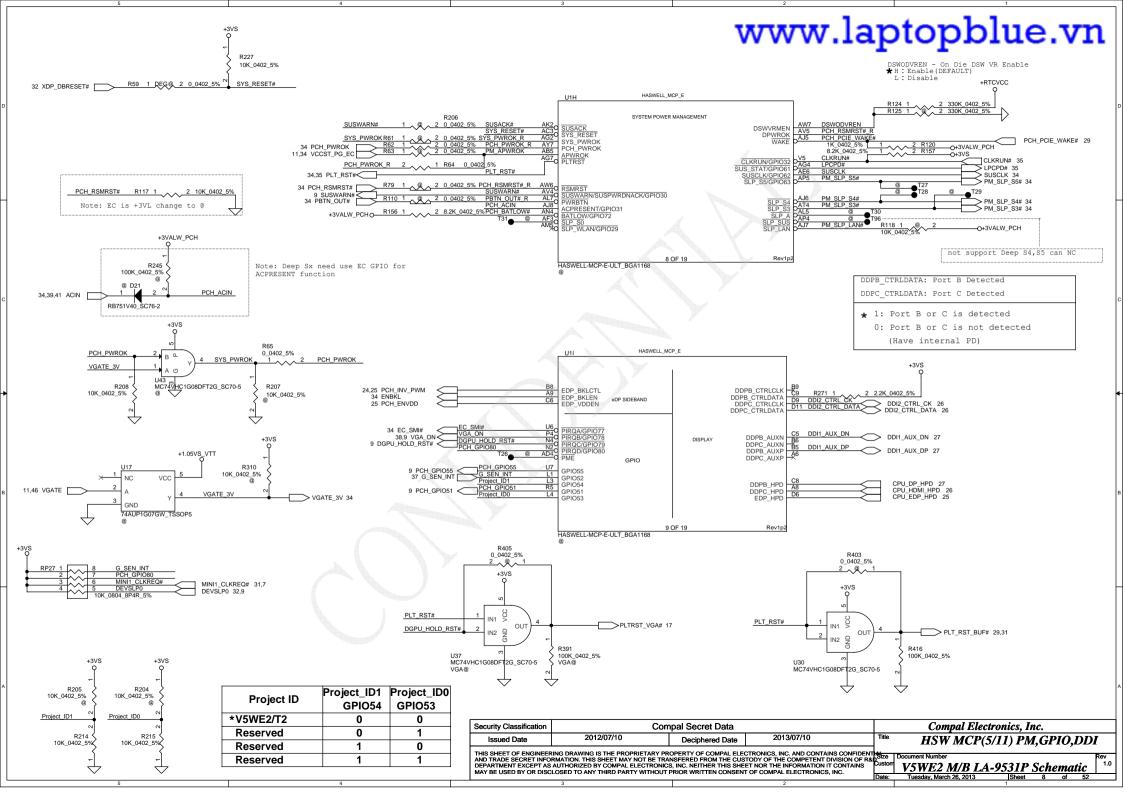
Security Classification	Con	npal Secret Data			Compal Electronics, Inc.
Issued Date	2012/07/10	Deciphered Date	2013/07/10	Title	HSW MCP(2/11) DDRIII
DEPARTMENT EXCEPT AS	RING DRAWING IS THE PROPRIETARY PR RMATION. THIS SHEET MAY NOT BE TRA AUTHORIZED BY COMPAL ELECTRONIC LOSED TO ANY THIRD PARTY WITHOUT	S, INC. NEITHER THIS SHE	ET NOR THE IN CRIMATION TO CONTAINS	Size Custom	Document Number V5WE2 M/B LA-9531P Schematic 1.0

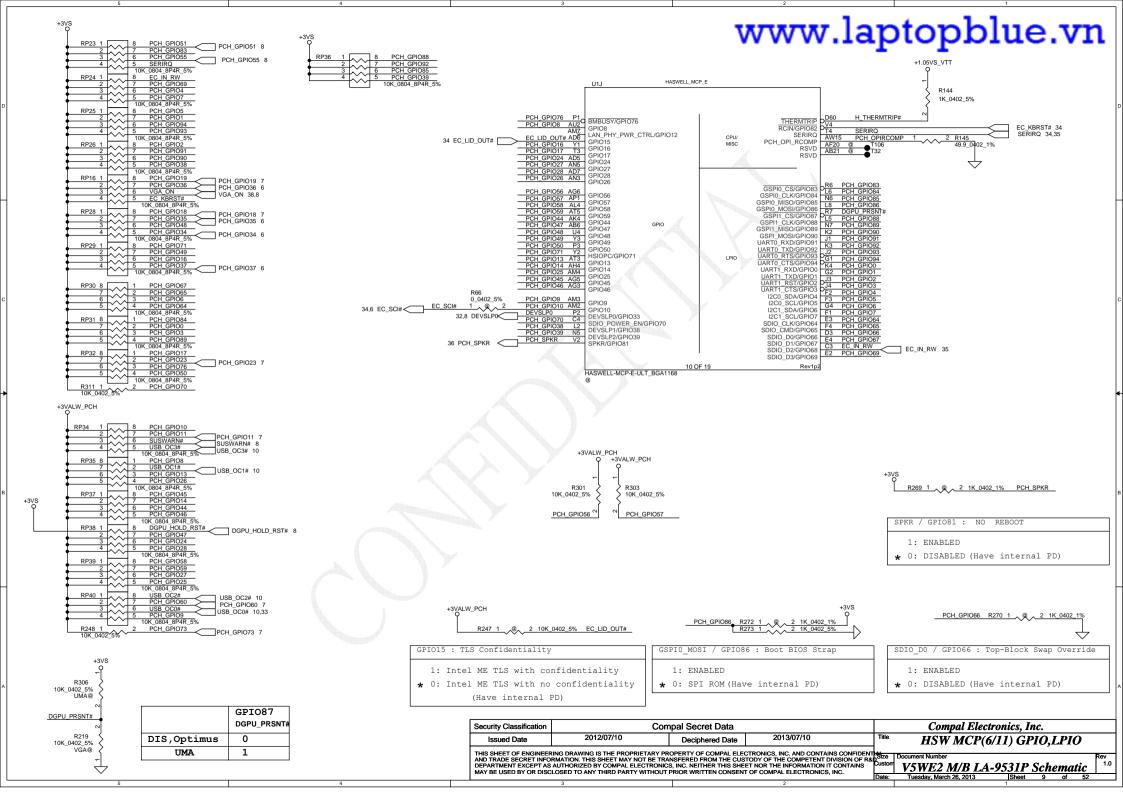
Tuesday, March 26, 2013

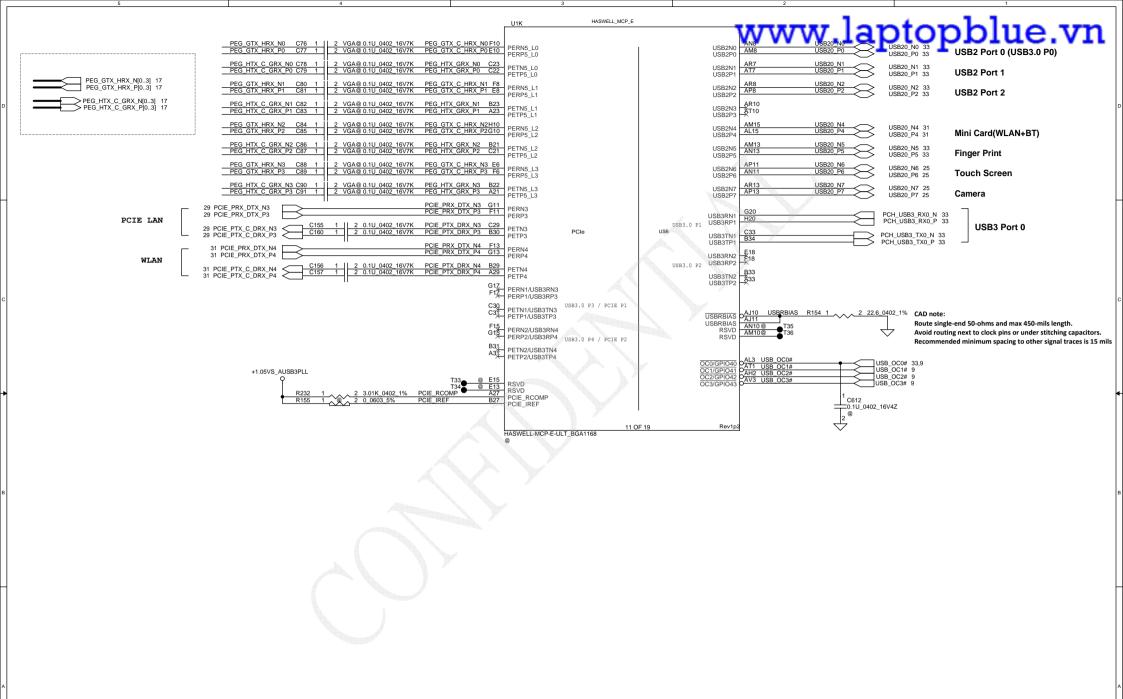
Sheet 5



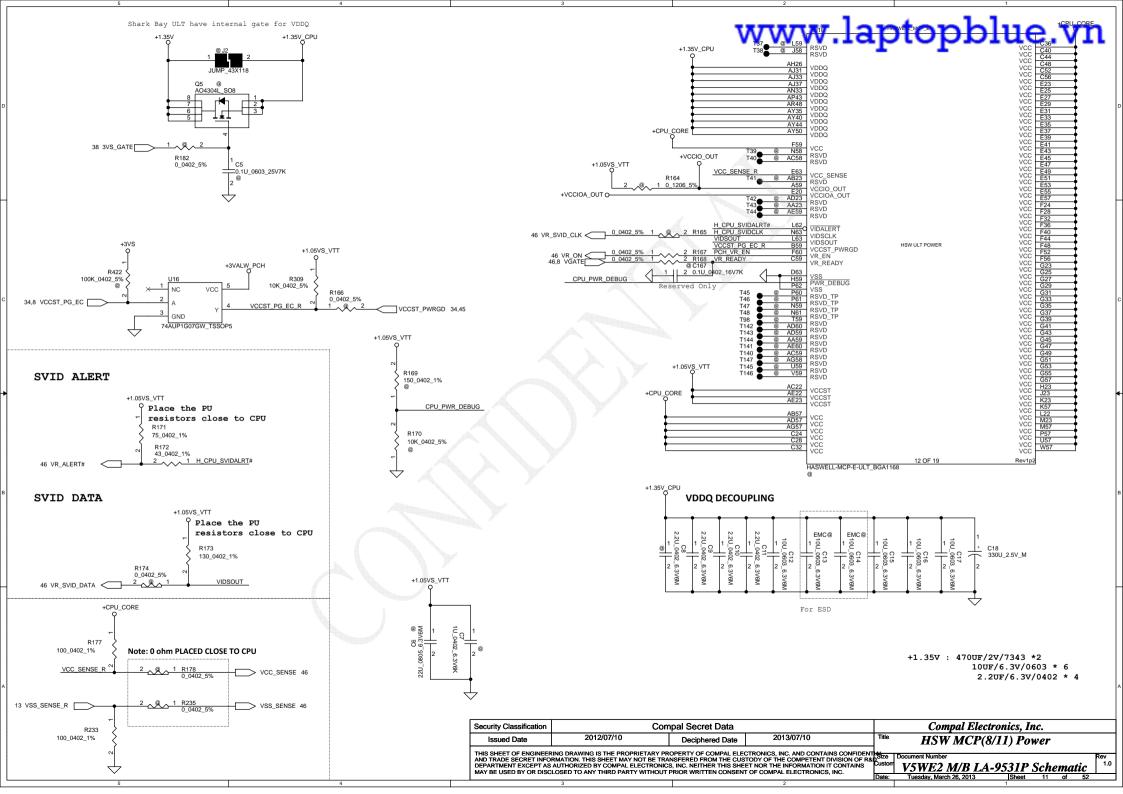


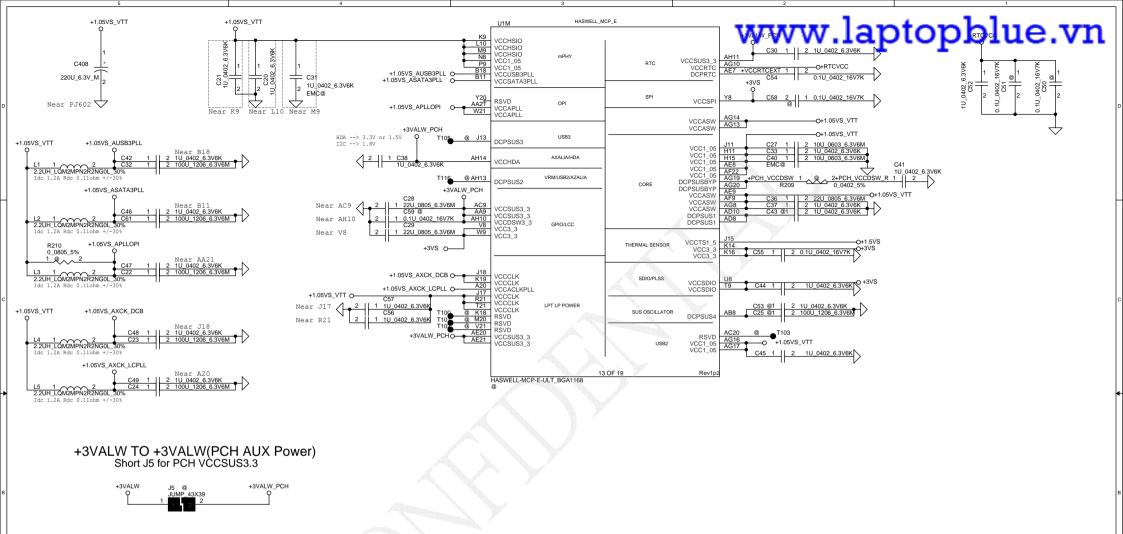






Security Classification	Cor	mpal Secret Data			Compal Electronics, Inc.	
Issued Date	2012/07/10	Deciphered Date	2013/07/10	Title	HSW MCP(7/11) PCIE,USB	
DEPARTMENT EXCEPT AS	RING DRAWING IS THE PROPRIETARY P RMATION. THIS SHEET MAY NOT BE TR AUTHORIZED BY COMPAL ELECTRONIC LOSED TO ANY THIRD PARTY WITHOUT	CS, INC. NEITHER THIS SHE	CTRONICS, INC. AND CONTAINS CONFIDENT TODY OF THE COMPETENT DIVISION OF R& ET NOR THE INFORMATION IT CONTAINS IT OF COMPAL ELECTRONICS, INC.	Size Custon	Document Number V5WE2 M/B LA-9531P Schematic Tuesday March 26 2013 Sheet 10 of 52	Rev 1.0



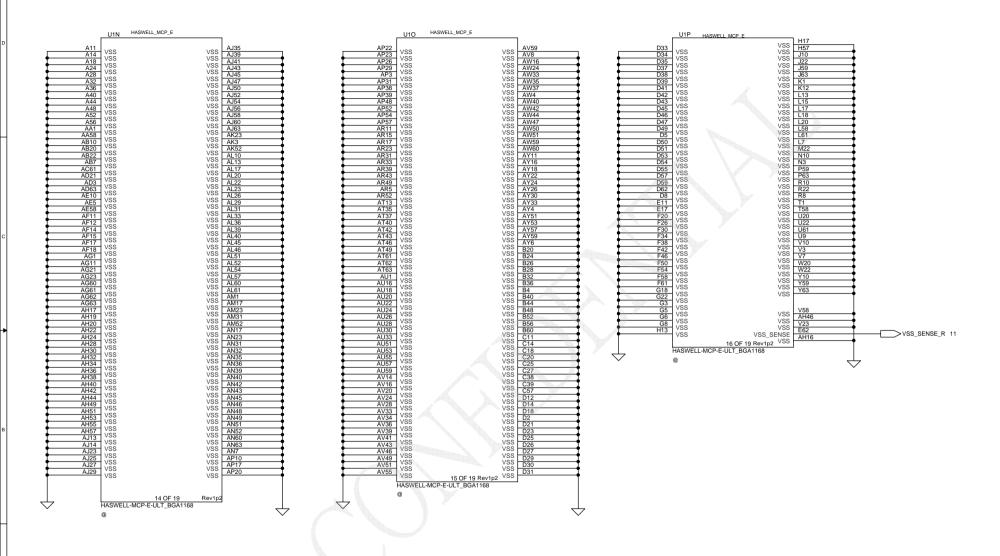


Security Classification Compal Secret Data

Issued Date 2012/07/10 Deciphered Date 2013/07/10 Title HSW MCP(9/11) Power

THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENT MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTER THIS SHEET NOR THE INFORMATION THE INFORMATION TO A SHEET MAY HOT BE TRANSFERED FROM THE CLISTOPY OF THE COMPETENT DIVISION OF RASSED DECUMENT NUMBER USED BY COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENT MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.

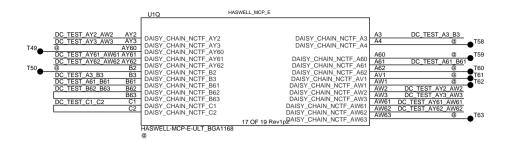
| Rev | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1

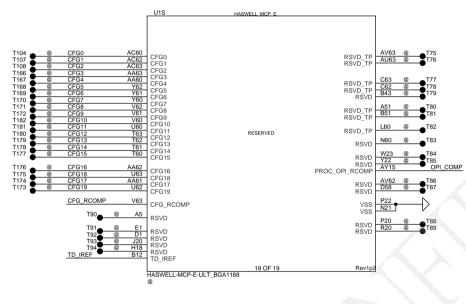


Security Classification	Con	npal Secret Data		Compal Electronics, Inc.	
Issued Date	2012/07/10	Deciphered Date	2013/07/10	Title HSW MCP(10/11) GND	
DEPARTMENT EXCEPT AS		S, INC. NEITHER THIS SHE	ET NOR THE IN ORMATION TO CONTAINS	Size Document Number V5WE2 M/B LA-9531P Schematic	Rev 1.0

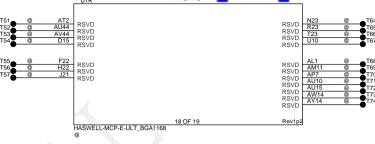
Tuesday, March 26, 2013

Sheet 13 of

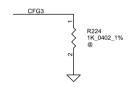




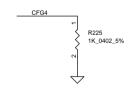




CFG Straps for Processor



Physical	Debug Enable (DFX Privacy)
CFG3	1: DISABLED
CFGS	0: ENABLED; SET DFX ENABLED BIT IN DEBUG INTERFACE MSR

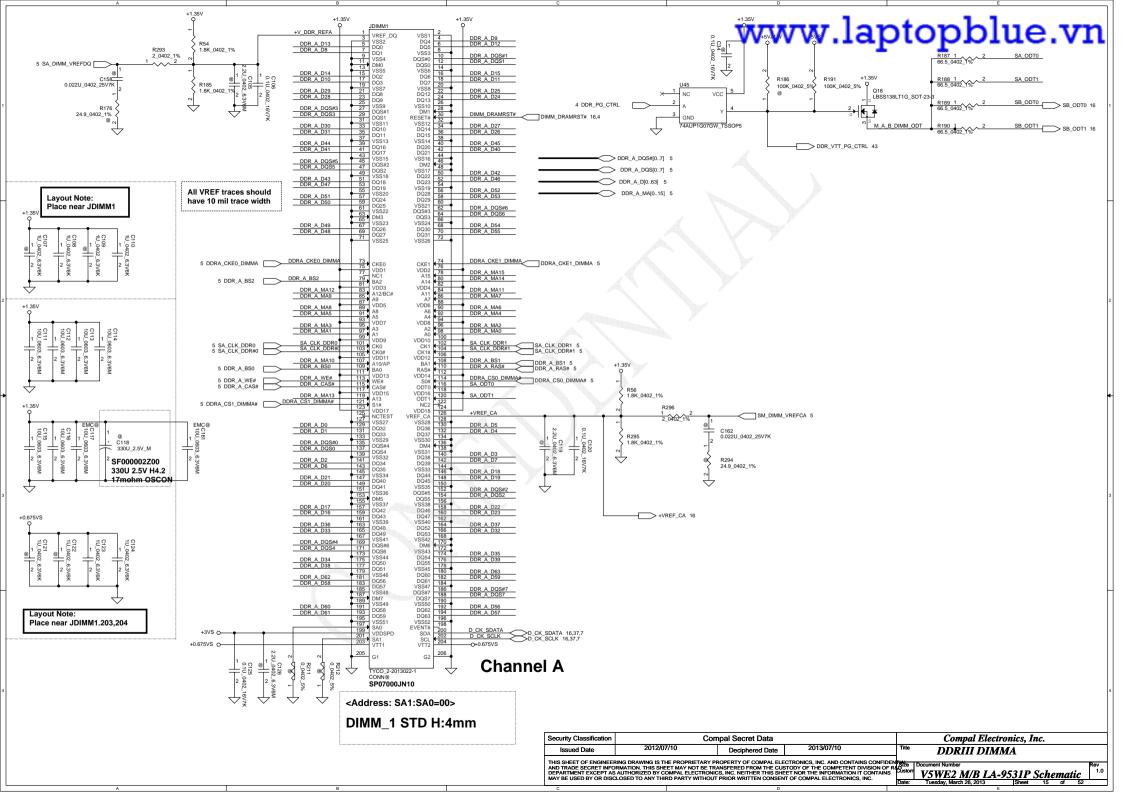


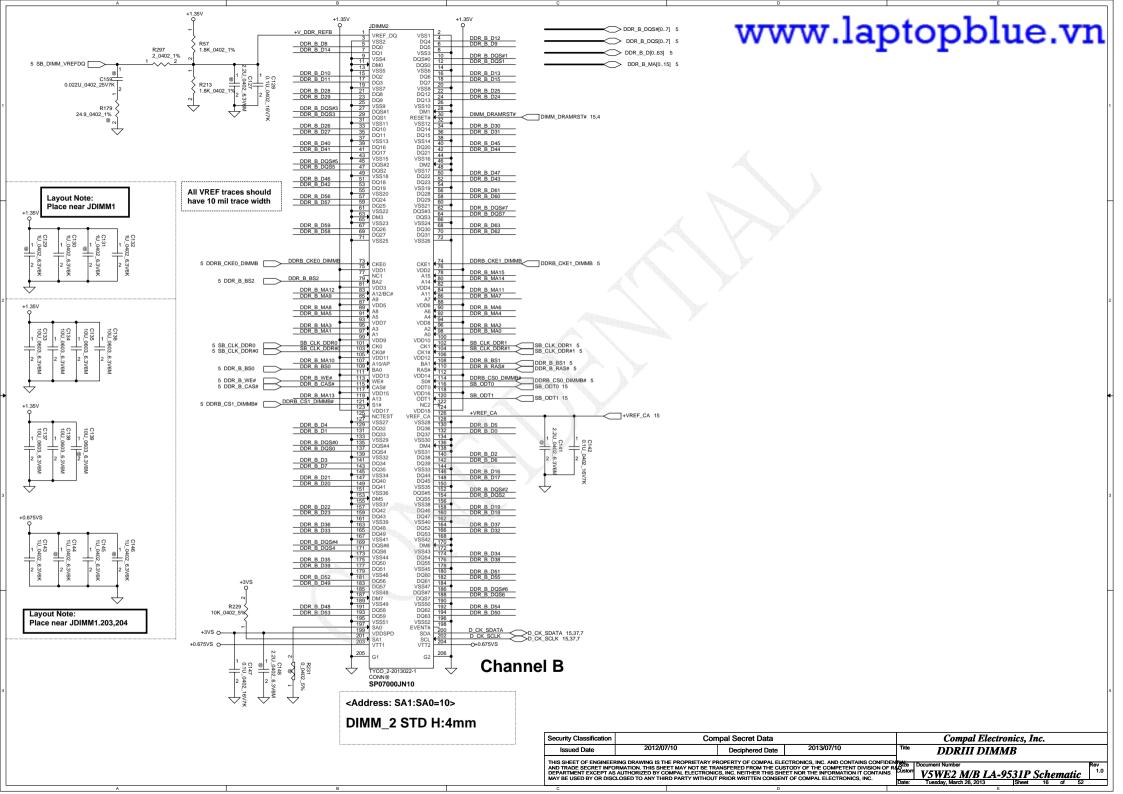
Display 1	Display Port Presence Strap						
CFG4	1 : Disabled; No Physical Display Port attached to Embedded Display Port						
	0 : Enabled; An external Display Port device is connected to the Embedded Display Port						

Tuesday, March 26, 2013

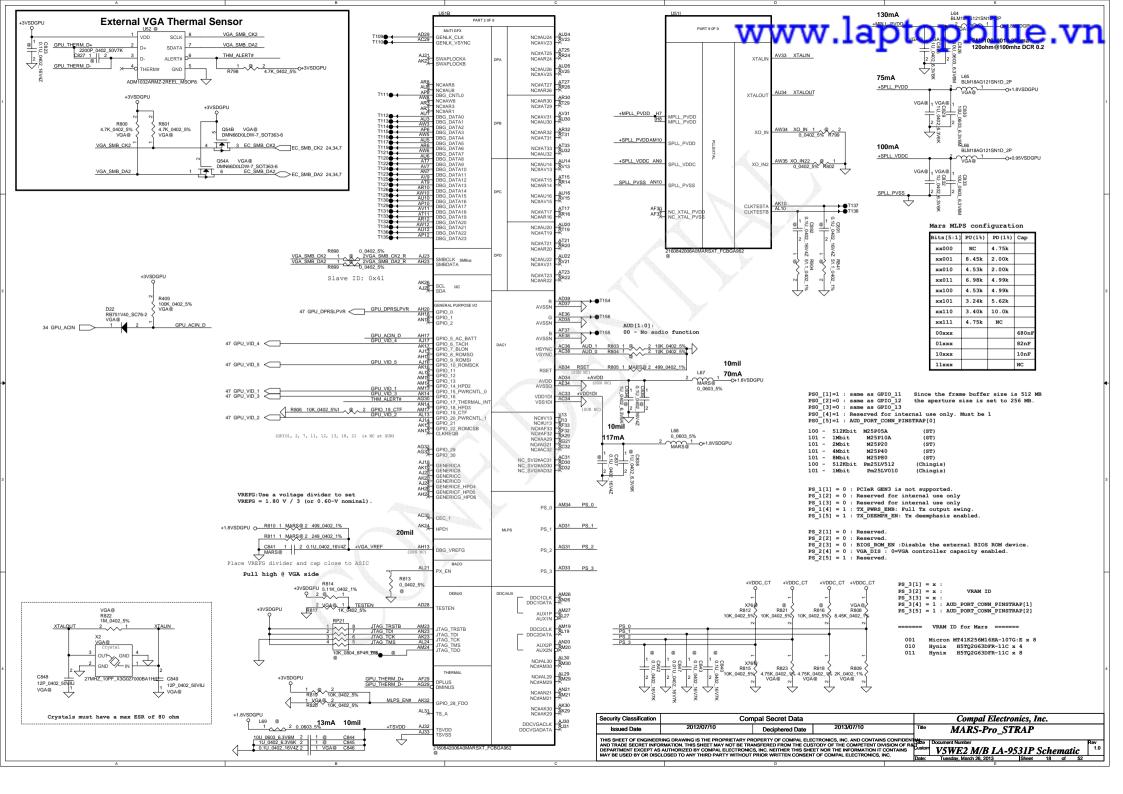
Sheet 14 of 52

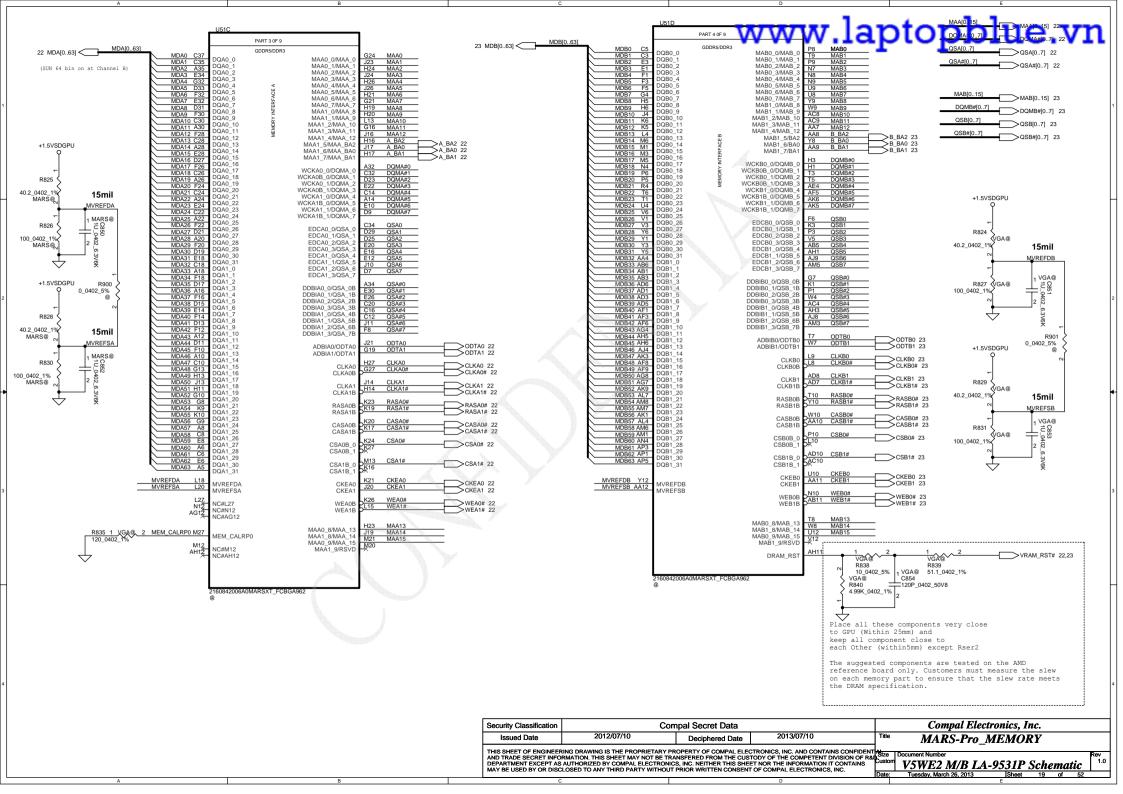
Security Classification					Compal Electronics, Inc.
Issued Date	2012/07/10	Deciphered Date	2013/07/10	Title	HSW MCP(11/11) RSVD
DEPARTMENT EXCEPT AS	RING DRAWING IS THE PROPRIETARY PR RMATION. THIS SHEET MAY NOT BE TRA AUTHORIZED BY COMPAL ELECTRONIC LOCED TO ANY THIS DABTY WITHOUT	Size Custor	Document Number V5WE2 M/B LA-9531P Schematic Rev 1.0		

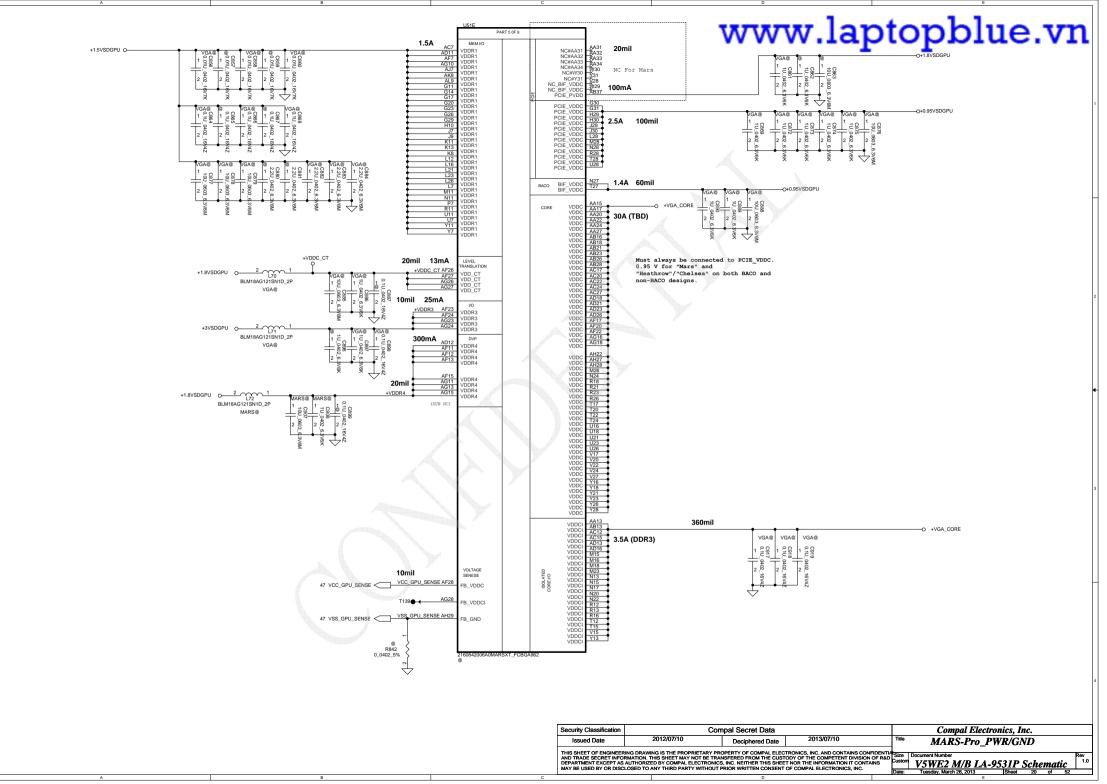


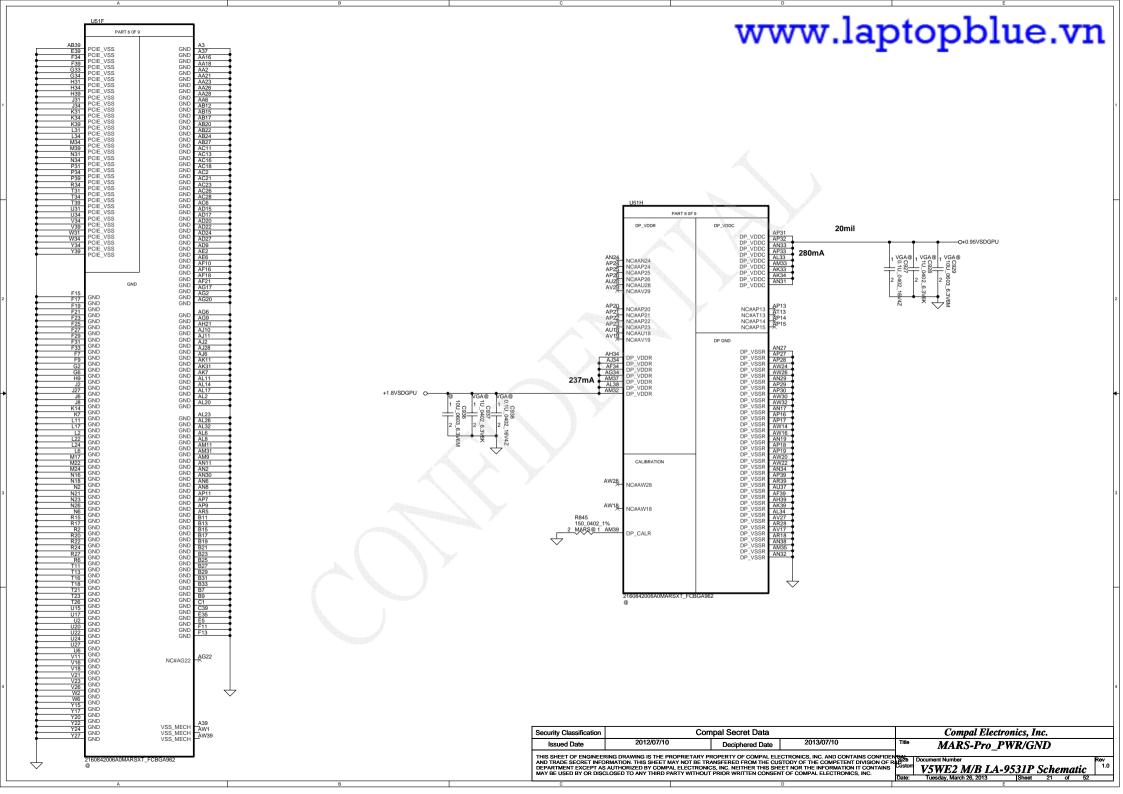


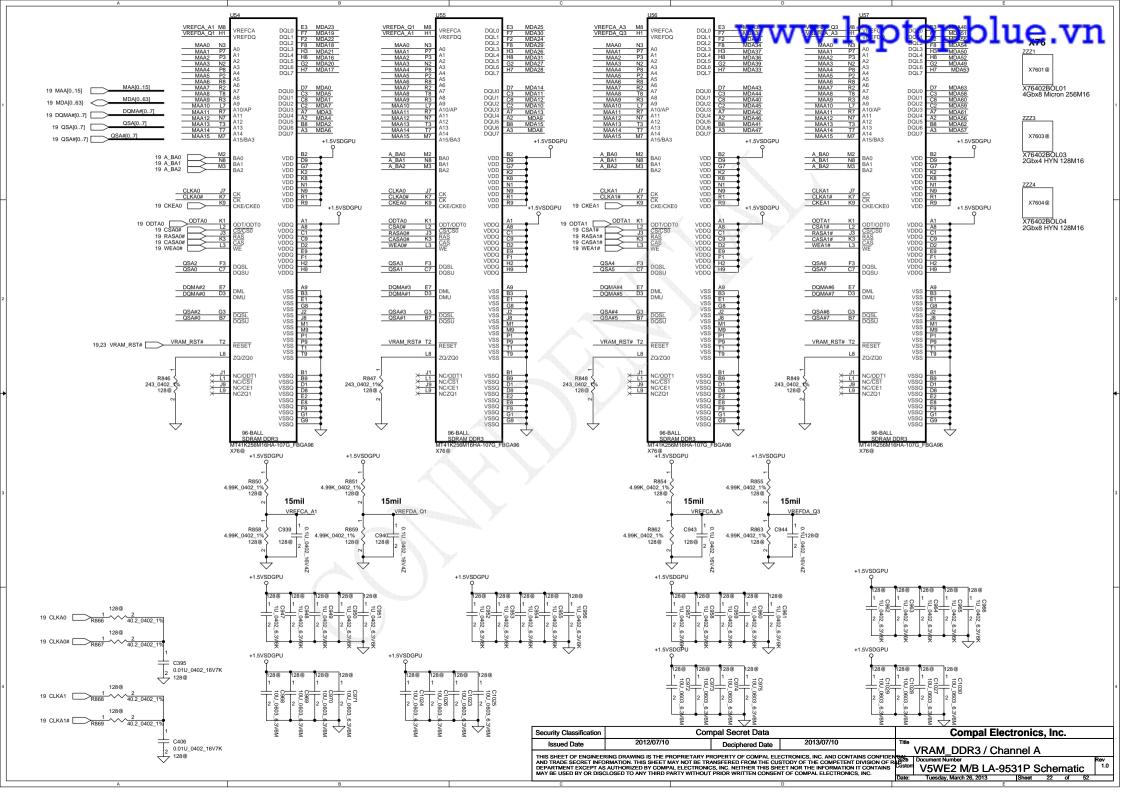
www.laptopblue.vn GFX PCIE LANE REVERSAL 10 PEG_HTX_C_GRX_P[0..3] PART 1 0F 9 PEG_GTX_HRX_P[0..3] 10 PEG HTX C GRX NI0..31 10 PEG_HTX_C_GRX_N[0..3] PEG_GTX_HRX_N[0..3] PEG_GTX_HRX_N[0..3] 10 PCIE RX0P PART 7 0F 9 RSVD/VARY_BI PCIE RX1P LVDS CONTROL PEG_HTX_C_GRX_P2 PCIE_RX2P PCIE_RX2N PEG GTX HRX N2 TXCBM_DPB3N PEG HTX C GRX P3 PEG GTX HRX P3 TY3P DPR2P PCIF RX3P PCIE_TX3P PCIE TX3N TX3M DPB2N PCIE RX3N TX4P DPB1P PCIE_RX4P PCIE_TX4P PCIE_TX4N PCIE_RX4N TX5M DPB0N PCIE_TX5P T29 PCIE_TX5N X PCIE_RX5P PCIE_RX5N NC#AF35 NC#AG36 PCIF RX6P PCIE_TX6P PCIE_TX6N PCIE_RX6N TXCAP_DPA3P TXCAM_DPA3N PCIE RX7P PCIE TX7P PCIE_TX7N TX0P DPA2P NC#N38 NC#N33 NC#N32 TX2P_DPA0P TX2M_DPA0N NC#M35 NC#N30 NC#L36 NC#N29 NC#AN36 NC#L38 NC#AP37 NC#K37 NC#L32 NC#K35 NC#J36 NC#L29 NC#J38 NC#K33 NC#H35 NC#J33 NC#J32 NC#G38 NC#K29 NC#F35 NC#H33 NC#E37 PCIE_REFCLKF R794 1 VGA@ 2 1.69K_0402_1% __O+0.95VSDGPU Y30 VGA_PCIE_CALRP PCIE CALR T VGA PCIE CALRN R796 1 VGA@ 2 1K_0402_1% O+0.95VSDGPU PCIE_CALR_R 3.3-V tolerant 8 PLTRST_VGA# PERSTB Security Classification **Compal Secret Data** Compal Electronics, Inc. SUN_XT_M2_962P MARS XT M2 962P 2012/07/10 2013/07/10 Issued Date Deciphered Date **MARS-Pro PCIE** MARS@ SA00006G610 SA000061.120 THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENT AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERED FROM THE CUSTODY OF THE COMPETENT DIVISION OF RAD DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NETHER THIS SHEET IN FINE PROPRATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC. 1.0 V5WE2 M/B LA-9531P Schematic Thursday, April 11, 2013 Sheet 17 of

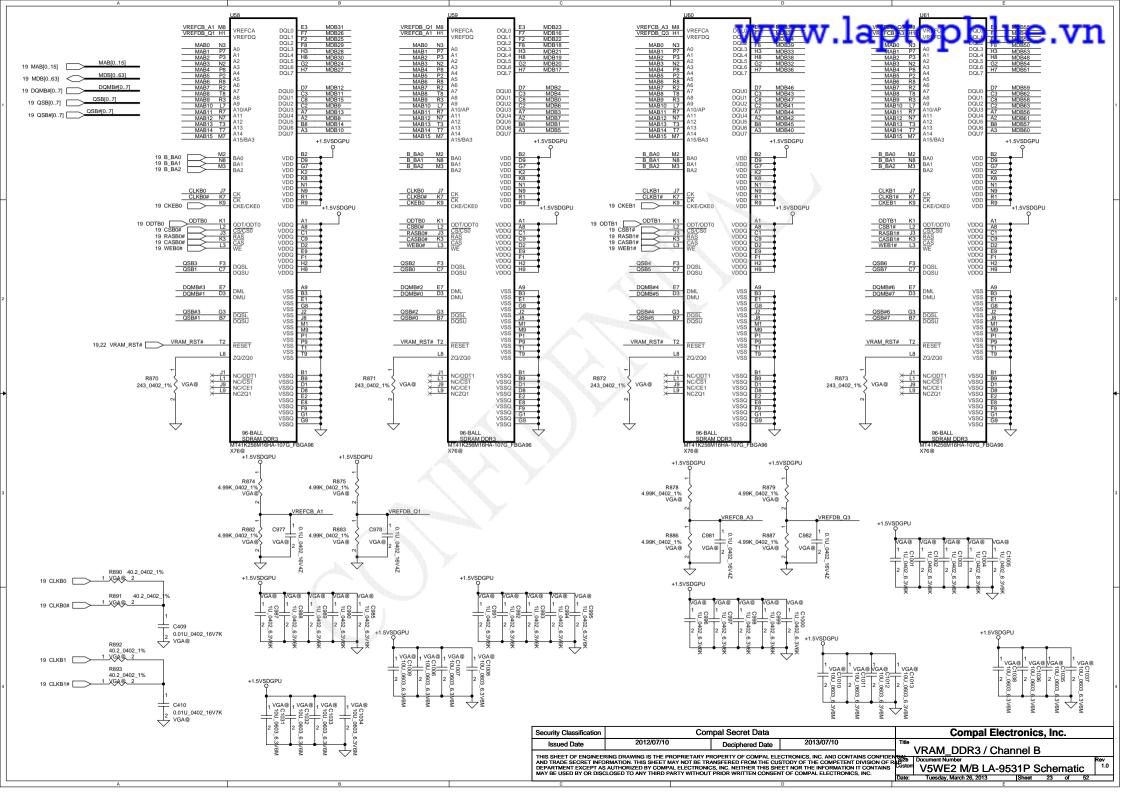


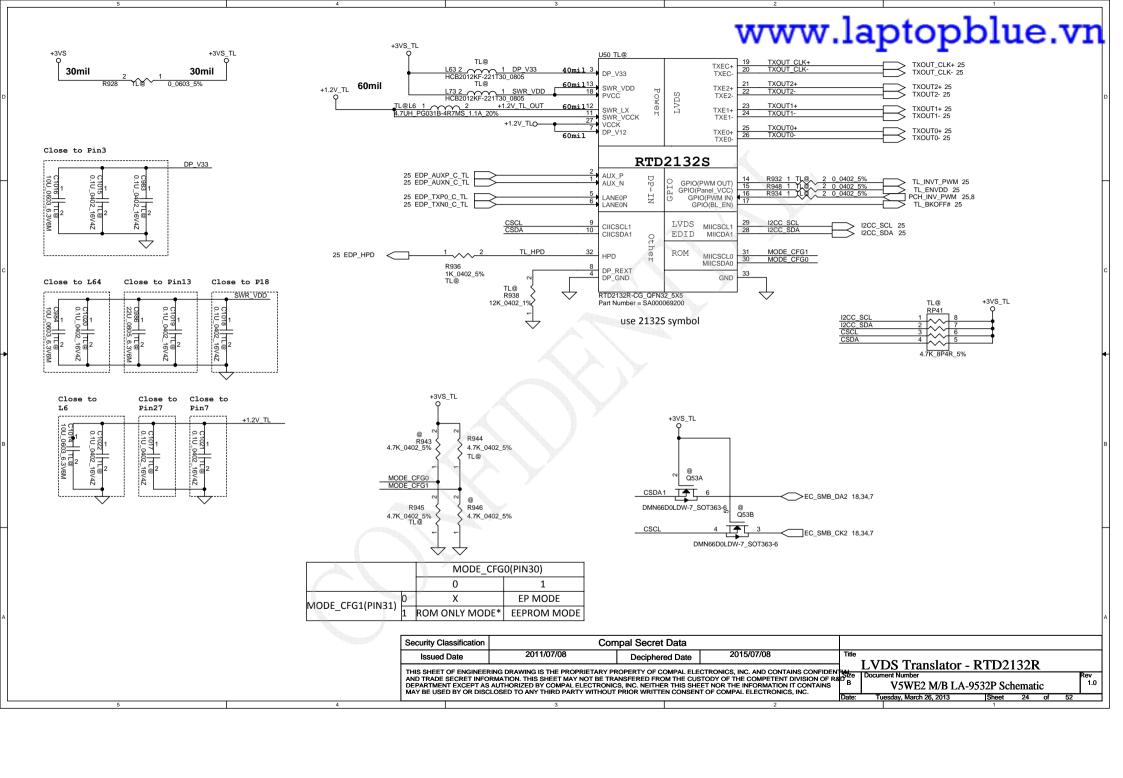


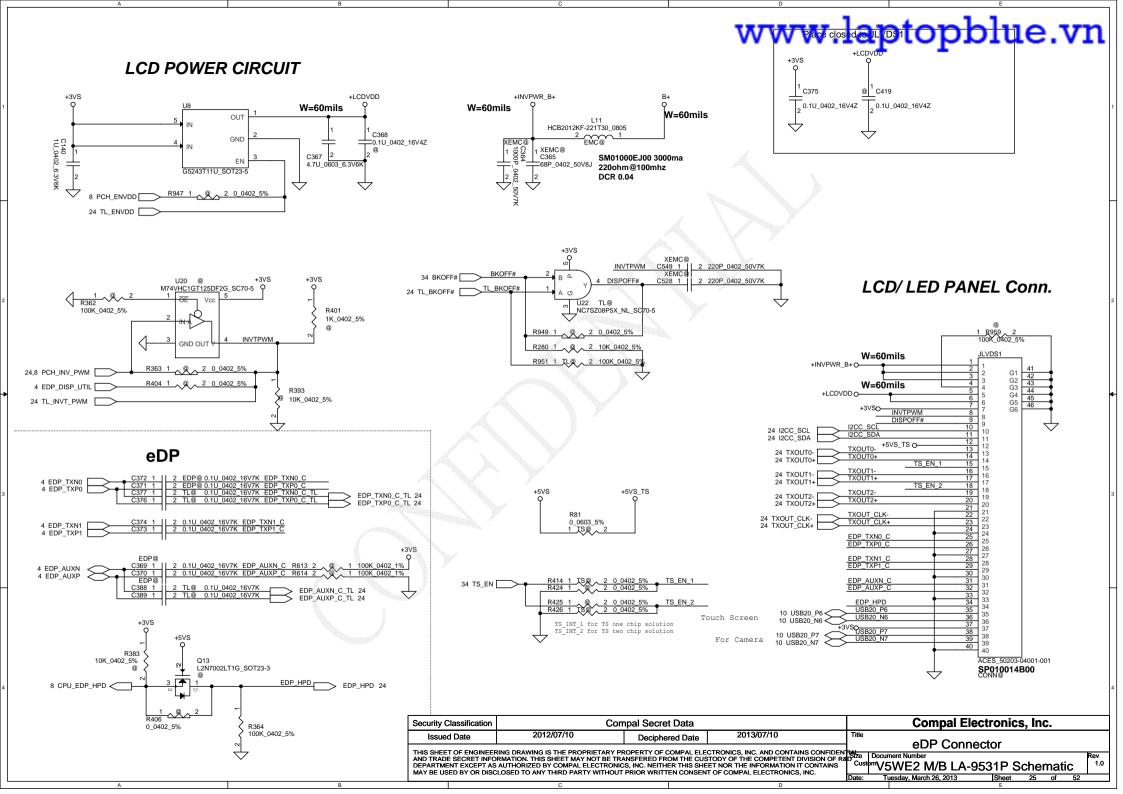


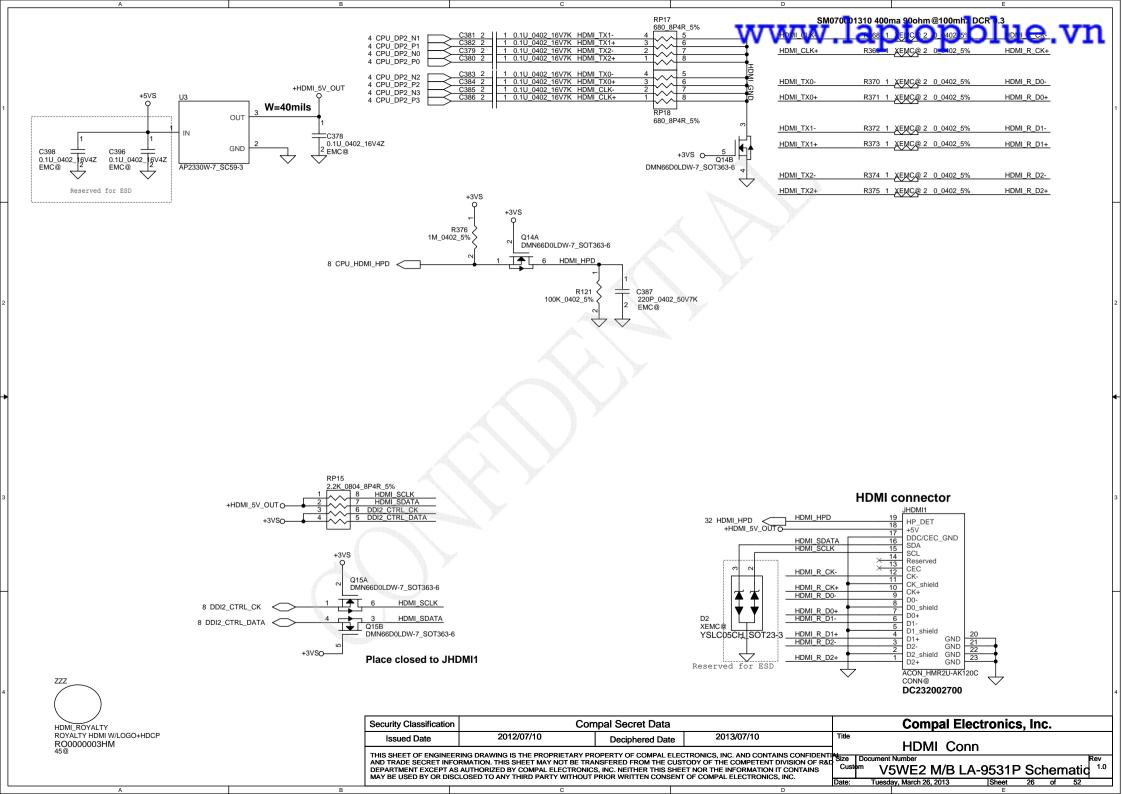


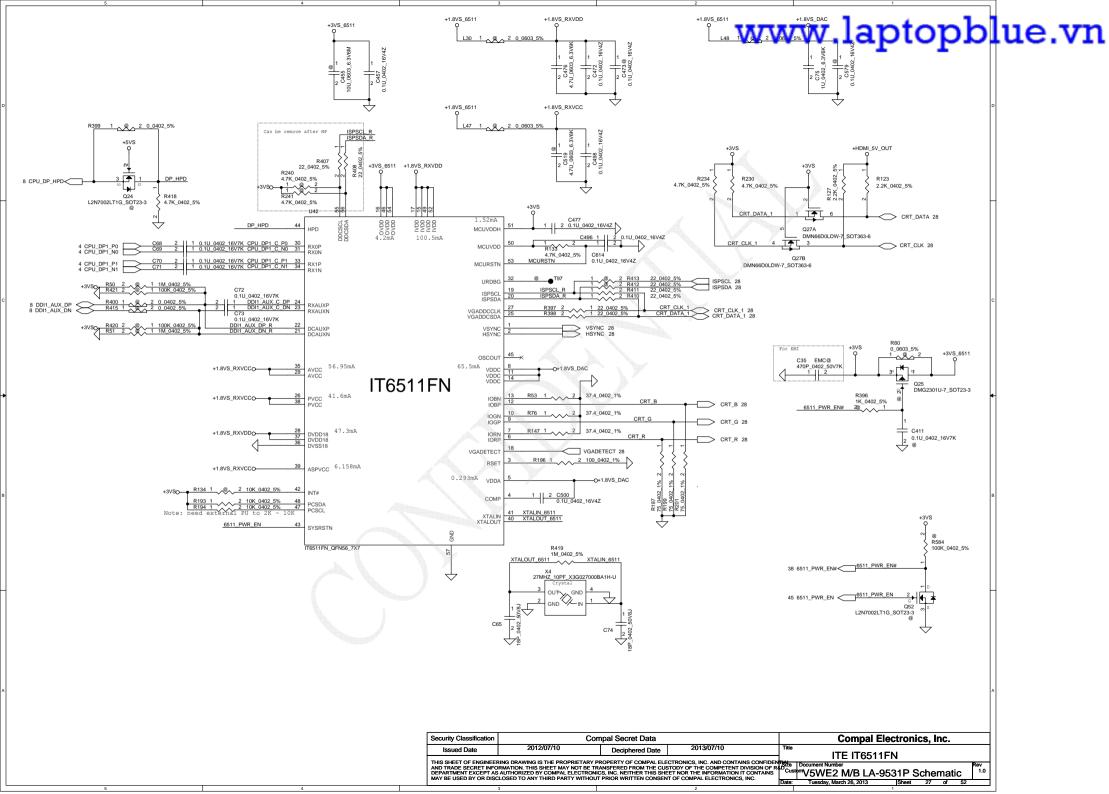


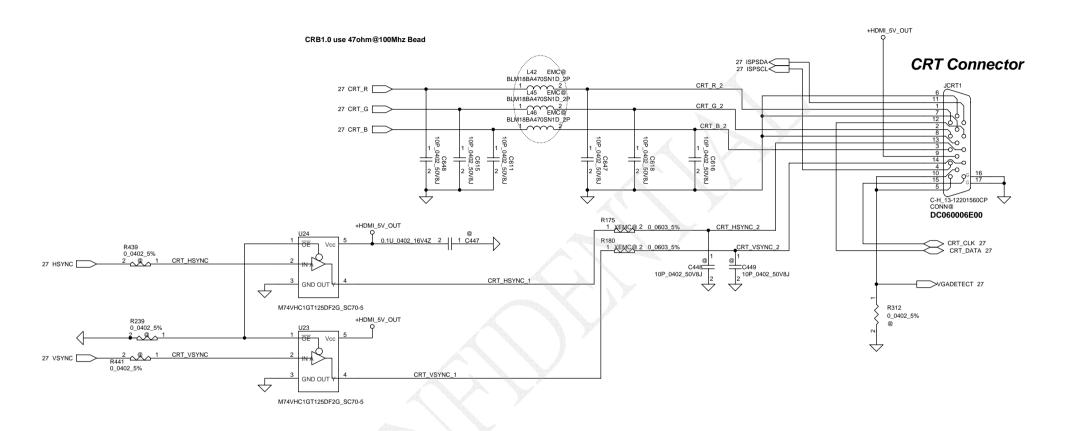


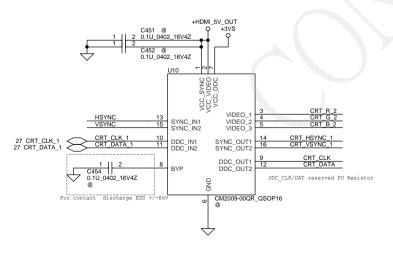




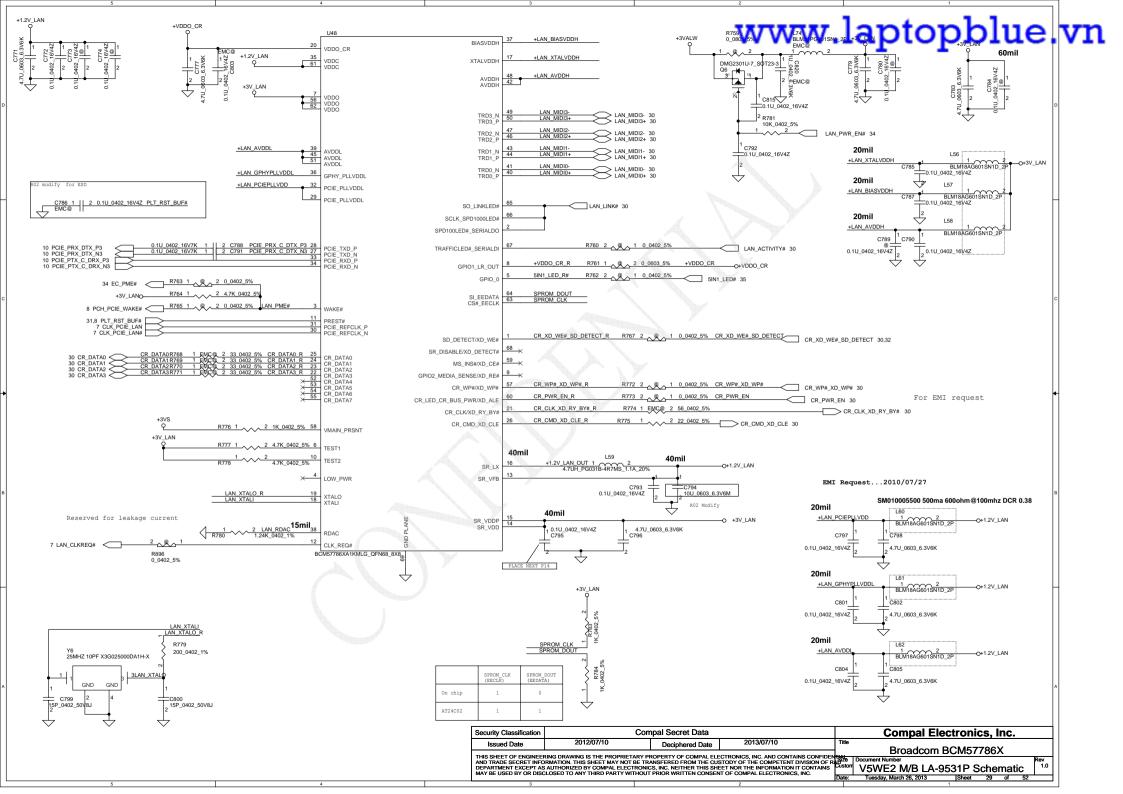


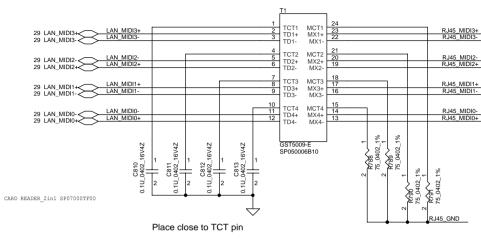






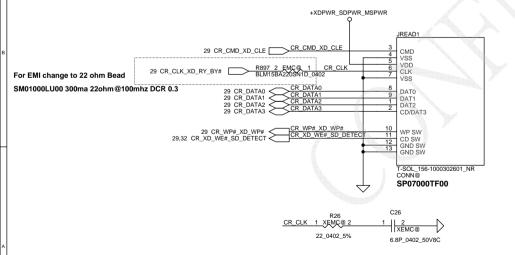
Security Classification	Com	npal Secret Data		Compal Electronics, Inc.	
Issued Date	2012/07/10	Deciphered Date	2013/07/10	CRT Connector	
THIS SHEET OF ENGINEER	RING DRAWING IS THE PROPRIETARY PR	OPERTY OF COMPAL ELEC	CTRONICS, INC. AND CONTAINS CONFIDENT TODY OF THE COMPETENT DIVISION OF R&	CRT Connector	Rev
AND TRADE SECRET INFO DEPARTMENT EXCEPT AS	RMATION. THIS SHEET MAY NOT BE TRA AUTHORIZED BY COMPAL ELECTRONIC	INSFERED FROM THE CUS S, INC. NEITHER THIS SHE	TODY OF THE COMPETENT DIVISION OF R& ET NOR THE INFORMATION IT CONTAINS	CustomV5WE2 M/B LA-9531P Schematic	1.0
MAY BE USED BY OR DISC	I OSED TO ANY THIRD PARTY WITHOUT	PRIOR WRITTEN CONSENT	T OF COMPAL ELECTRONICS, INC.	TOTALE MADE TOOCH CONTINUES	

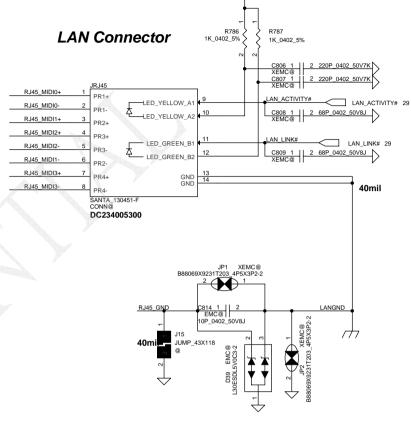


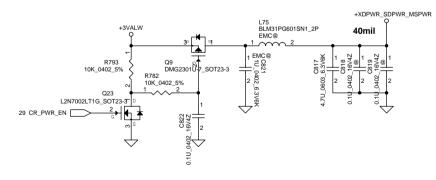


BOTHHAND: S X'FORM_ GST5009-E LF LAN, SP050006B10 TIMAG:S X'FORM_ IH-160 LAN , SP050006F00 MHPC:S X'FORM NS892403 LAN , SP050008500

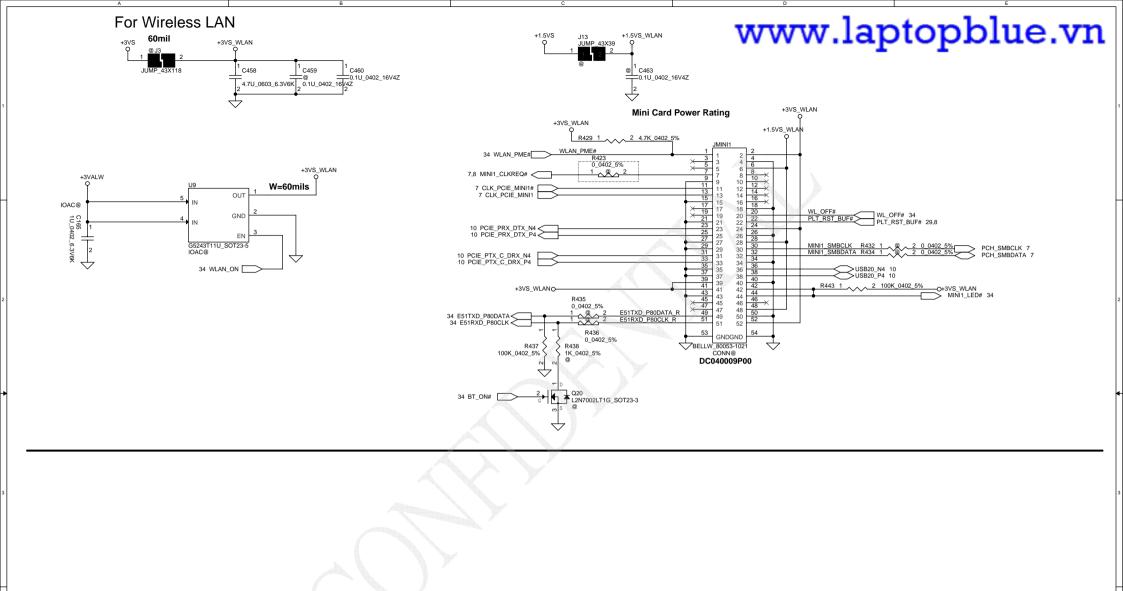
Card Reader Connector







Security Classification	11 12 12 12 12 12 12 12				Compal Electronics, Inc.
Issued Date	2012/07/10	Deciphered Date	2013/07/10	Title	LAN Magnetic & RJ45
THIS SHEET OF ENGINEER	RING DRAWING IS THE PROPRIETARY PR	Tistze	Document Number Rev		
DEPARTMENT EXCEPT AS	AUTHORIZED BY COMPAL ELECTRONIC	Cus	*****V5WE2 M/B LA-9531P Schematic 1.0		
MAY BE USED BY OR DISC	LOSED TO ANY THIRD PARTY WITHOUT	Date:	Tuesday, March 26, 2013 Sheet 30 of 52		



Security Classification	Com	pal Secret Data			Compal Electronics, Inc.	
Issued Date	2012/07/10	Deciphered Date	2013/07/10	Title	MINI CARD (WLAN)	
THIS SHEET OF ENGINEER	THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDEN AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R				I Document Number	Rev
DEPARTMENT EXCEPT AS	RMATION. THIS SHEET MAY NOT BE TRAI AUTHORIZED BY COMPAL ELECTRONICS LOSED TO ANY THIRD PARTY WITHOUT F	S, INC. NEITHER THIS SHE	ET NOR THE INFORMATION IT CONTAINS	Cust	"V5WE2 M/B LA-9531P Schematic	1.0
MAT BE USED BY OR DISC	EOSED TO ANT THIRD PARTT WITHOUT	- RIOR WRITTEN CONSEN	OF COMPAL ELECTRONICS, INC.	Date:	Tuesday, March 26, 2013 Sheet 31 of 52	

SATA ODD Conn.

LTCX004HZ00

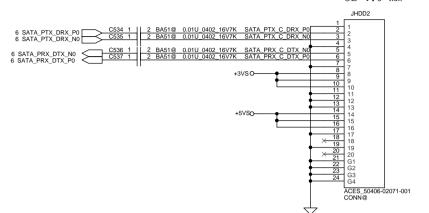
SATA HDD1 Conn.

G1

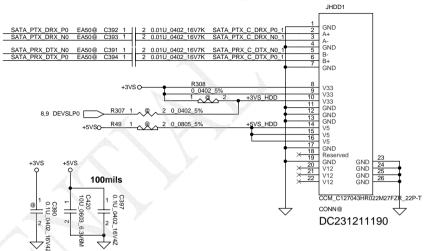
G2

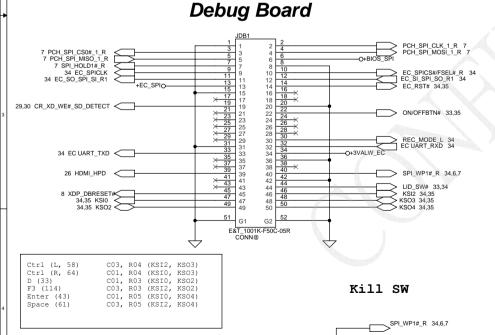
ACES 87212-02G0





SATA HDD1 Conn.





Security Classification Compal Secret Data

Issued Date 2012/07/10 Deciphered Date 2013/07/10

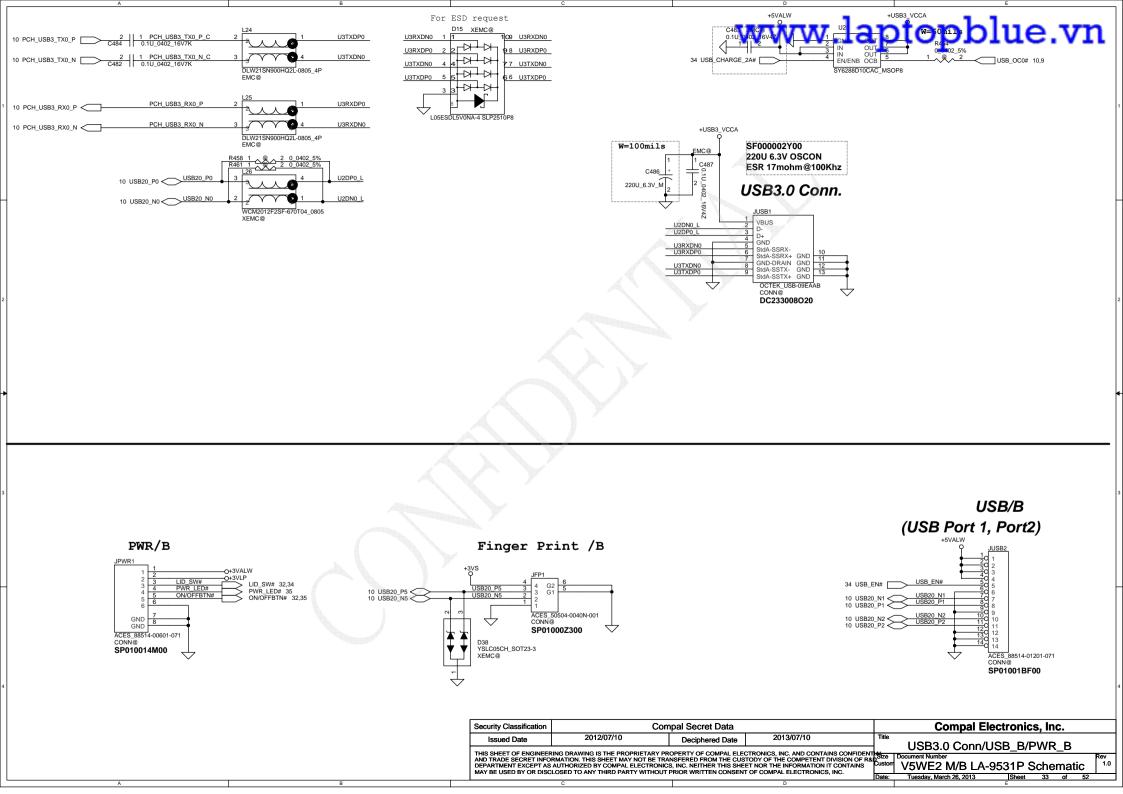
Title HDD/ODD/Debug Board

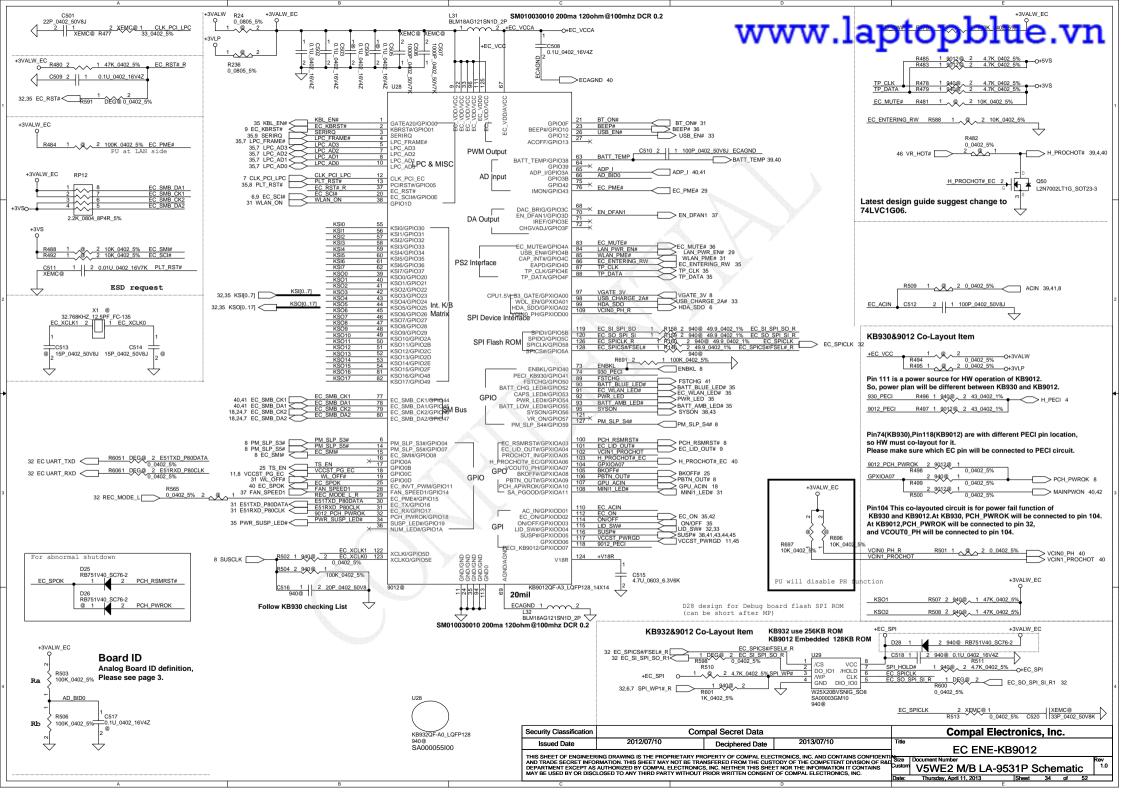
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENT AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERED FROM THE CLISTODY OF THE COMPETENT DIVISION OF RAD SECRET INFORMATION. TO CONTAINS

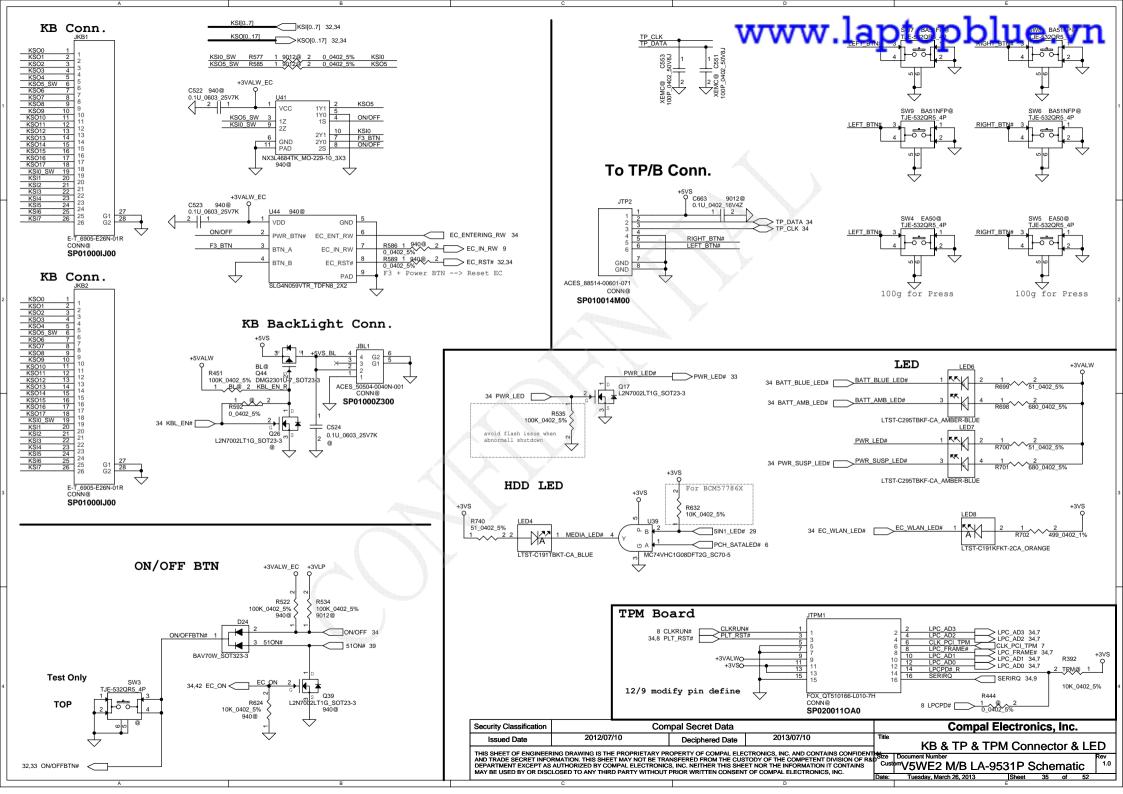
DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. AND CONTAINS

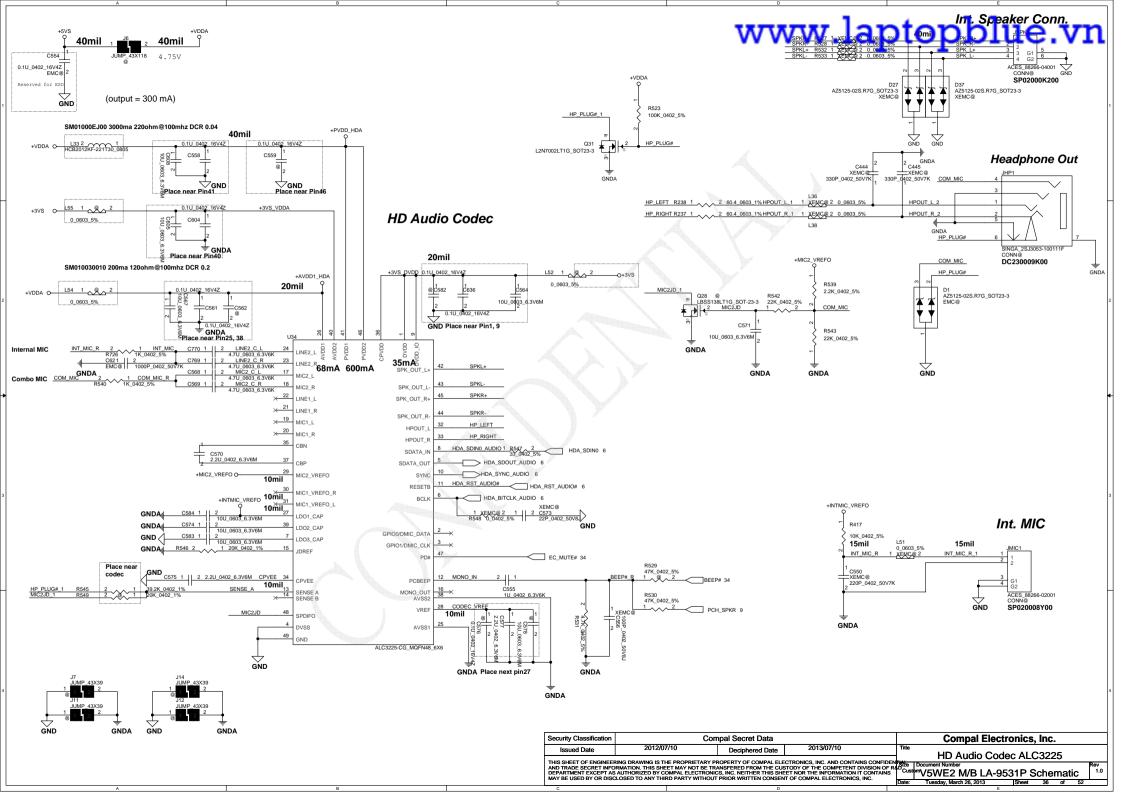
MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.

Date: Tuesday, March 26, 2013 Sheet 32 of 52









FAN1 Conn

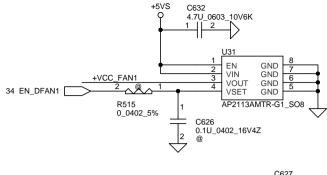
www.laptopblue.vn

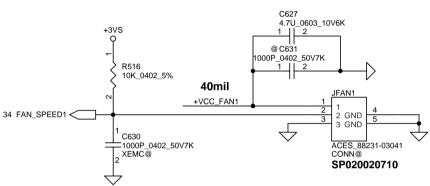
FIDUCIAL C40M80

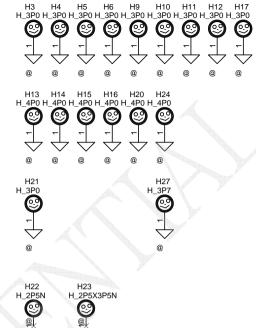
FIDUCIAL_C40M80

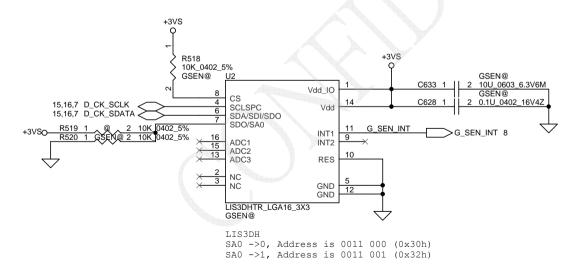
FIDUCIAL C40M80

FIDUCIAL_C40M80

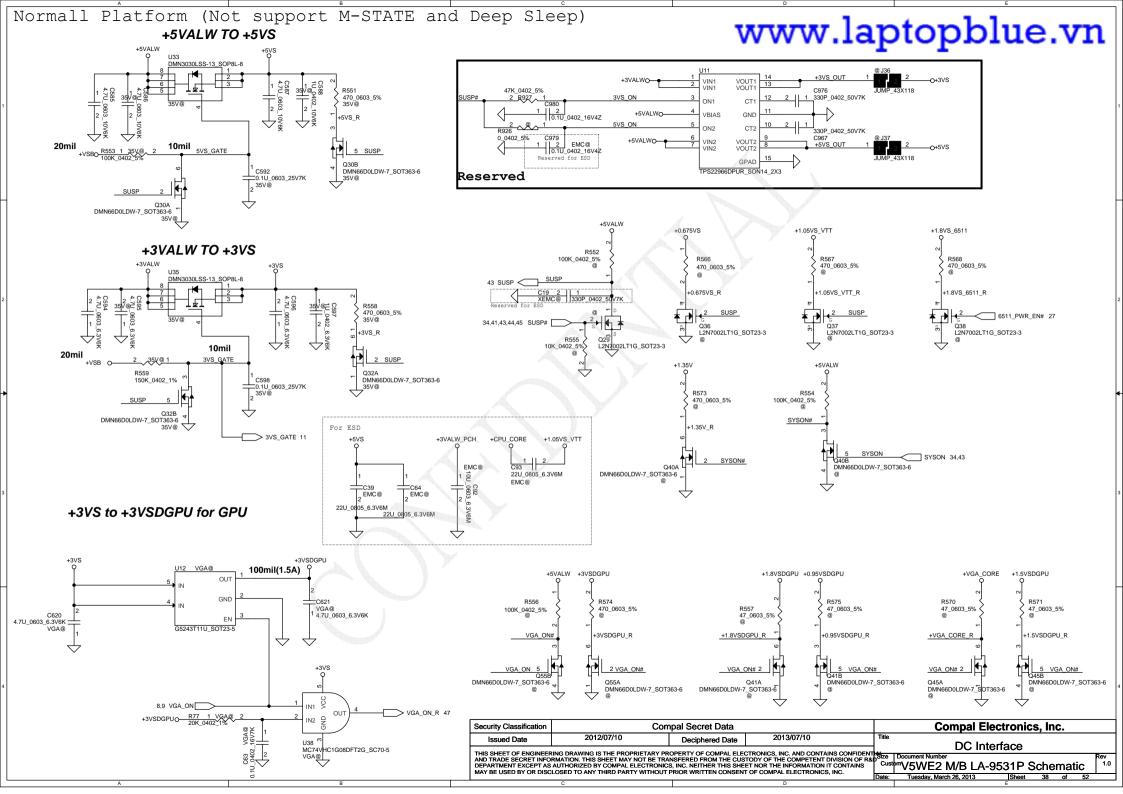


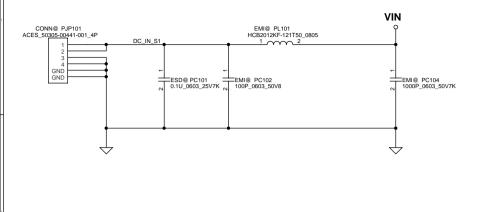


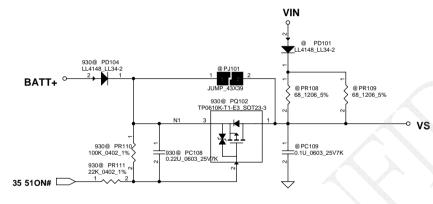




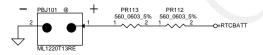
Security Classification	Coi	Compal Electronics, Inc.				
Issued Date	2012/07/10	Deciphered Date	2013/07/10	Title		
THIS SHEET OF ENGINEER	RING DRAWING IS THE PROPRIETARY P	ROPERTY OF COMPALIELE	CTRONICS INC. AND CONTAINS CONFIDEN	FAN & Screw Hole & G-Sensor		
			CTRONICS, INC. AND CONTAINS CONFIDEN STODY OF THE COMPETENT DIVISION OF R	Size Document Number Rev		
	AUTHORIZED BY COMPAL ELECTRONI "LOSED TO ANY THIRD PARTY WITHOU		ET NOR THE INFORMATION IT CONTAINS T OF COMPAL ELECTRONICS, INC.	CustomV5WE2 M/B LA-9531P Schematic 1.0		
				Date: Tuesday, March 26, 2013 Sheet 37 of 52		

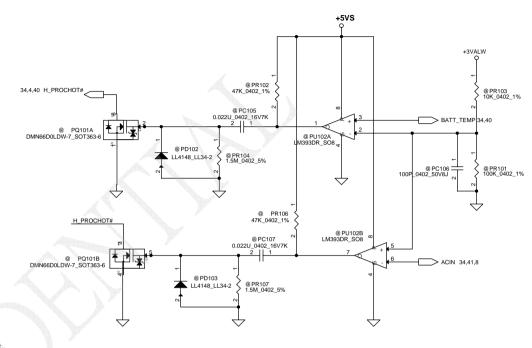




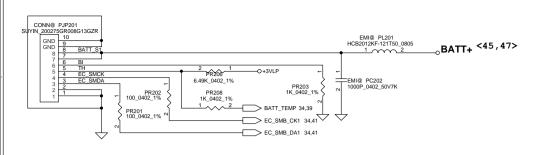






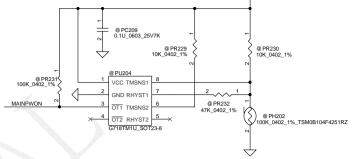


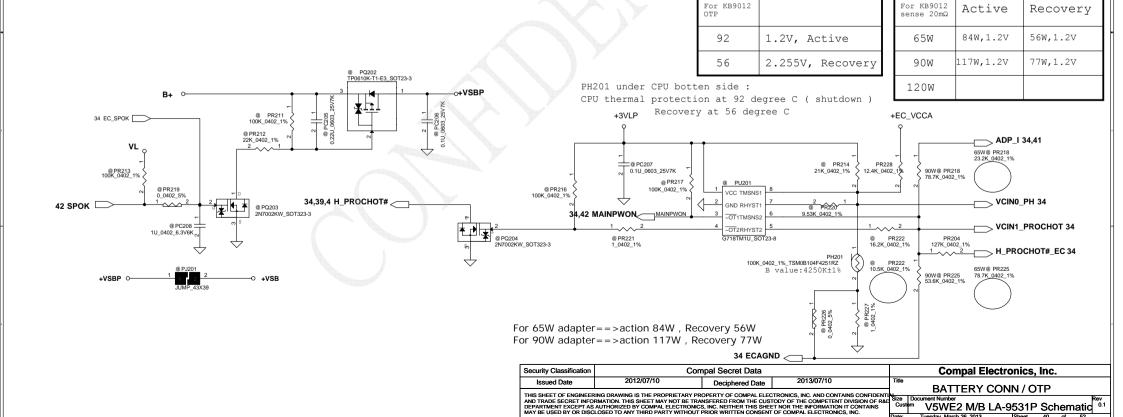
Security Classification	curity Classification Compal Secret Data				Compal Electronics, Inc.					
Issued Date	2012/07/10	Deciphered Date	2013/07/10	Title	DCIN				-	
THIS SHEET OF ENGINEER AND TRADE SECRET INFO DEPARTMENT EXCEPT AS MAY BE USED BY OR DISC	RING DRAWING IS THE PROPRIETARY PI RMATION. THIS SHEET MAY NOT BE TR. AUTHORIZED BY COMPAL ELECTRONIC LOSED TO ANY THIRD PARTY WITHOUT	ROPERTY OF COMPAL ELE ANSFERED FROM THE CUS S, INC. NEITHER THIS SHE PRIOR WRITTEN CONSEN	ECTRONICS, INC. AND CONTAINS CONFIDE STODY OF THE COMPETENT DIVISION OF F EET NOR THE INFORMATION IT CONTAINS IT OF COMPAL ELECTRONICS, INC.	Cust	Document Number om V5WE2 M/B LA- Tuesday, March 26, 2013	9531P	Sche	matic	Rev 0.1	

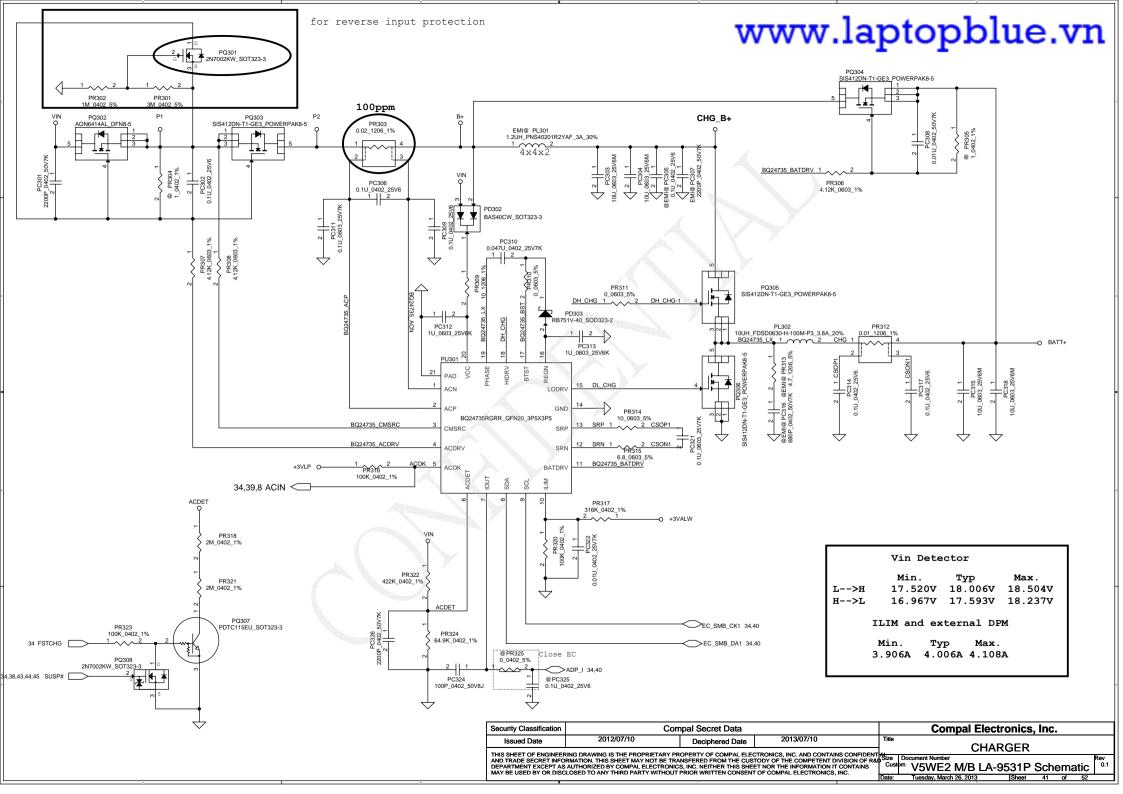


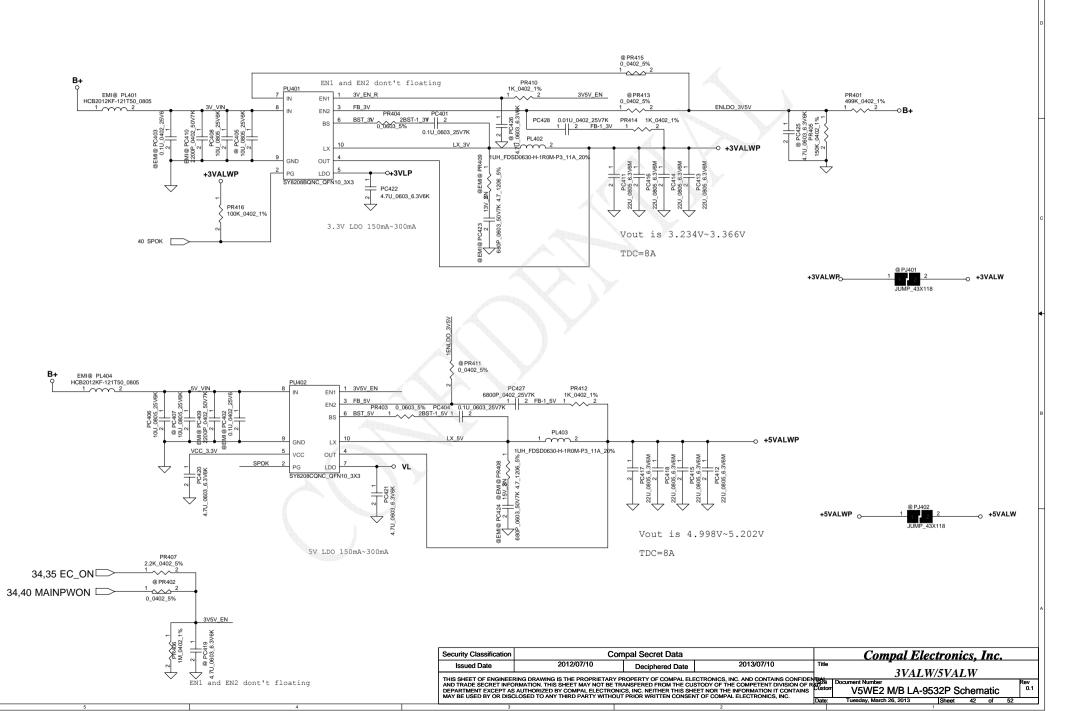


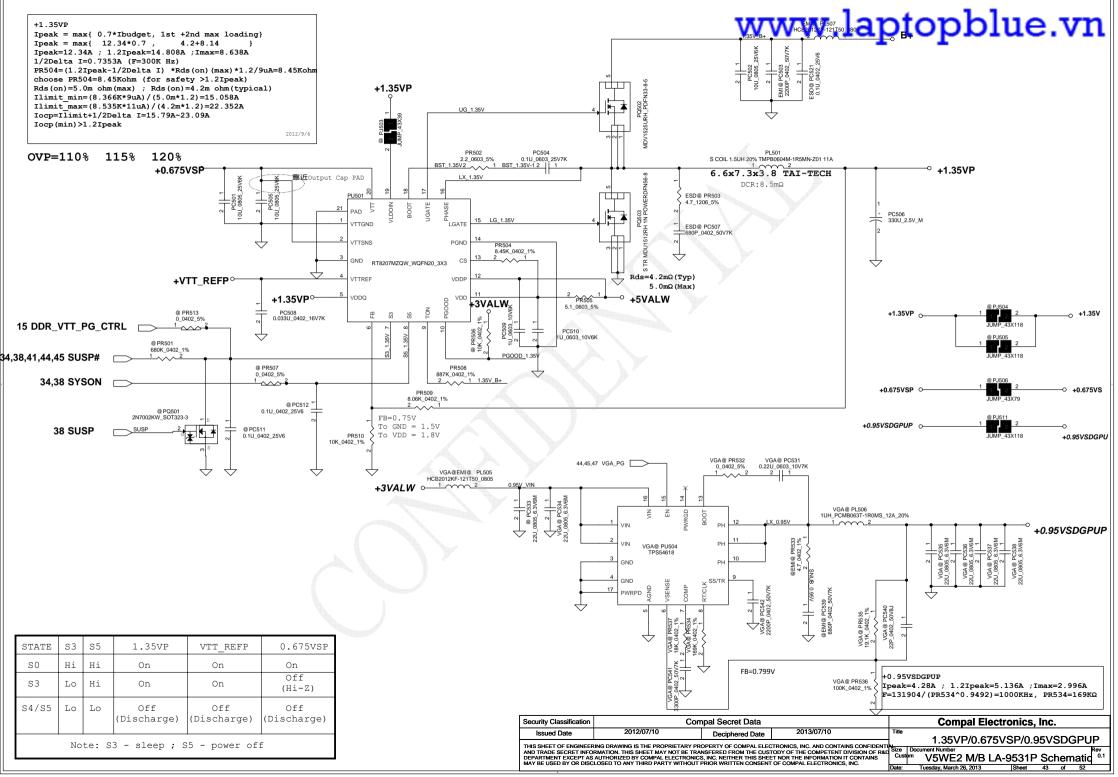
Tuesday, March 26, 2013

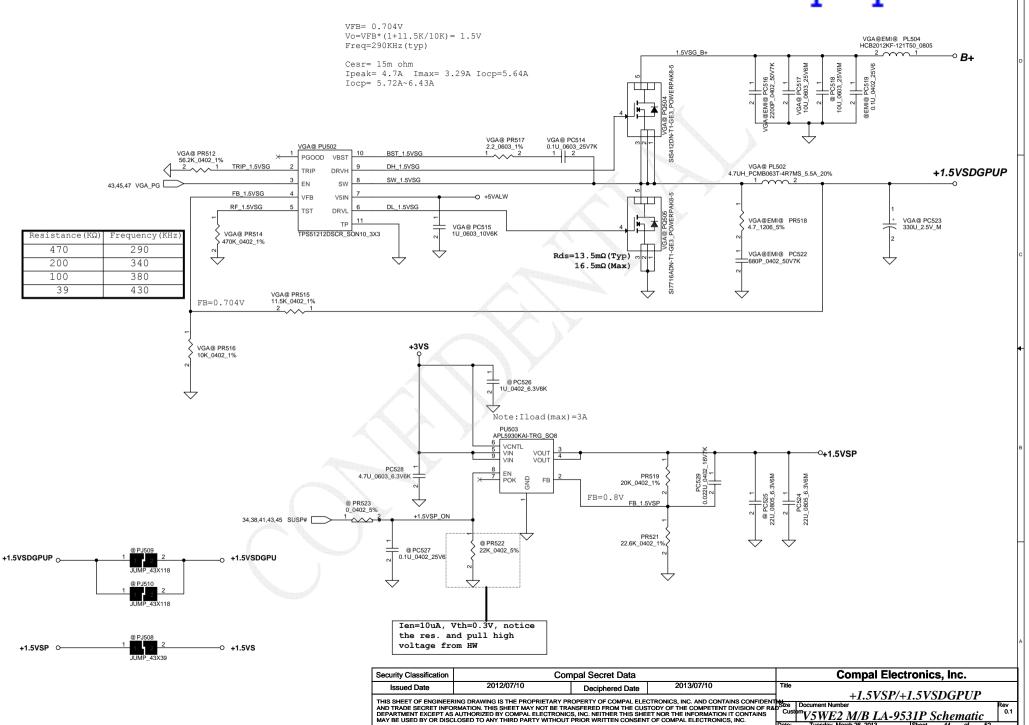


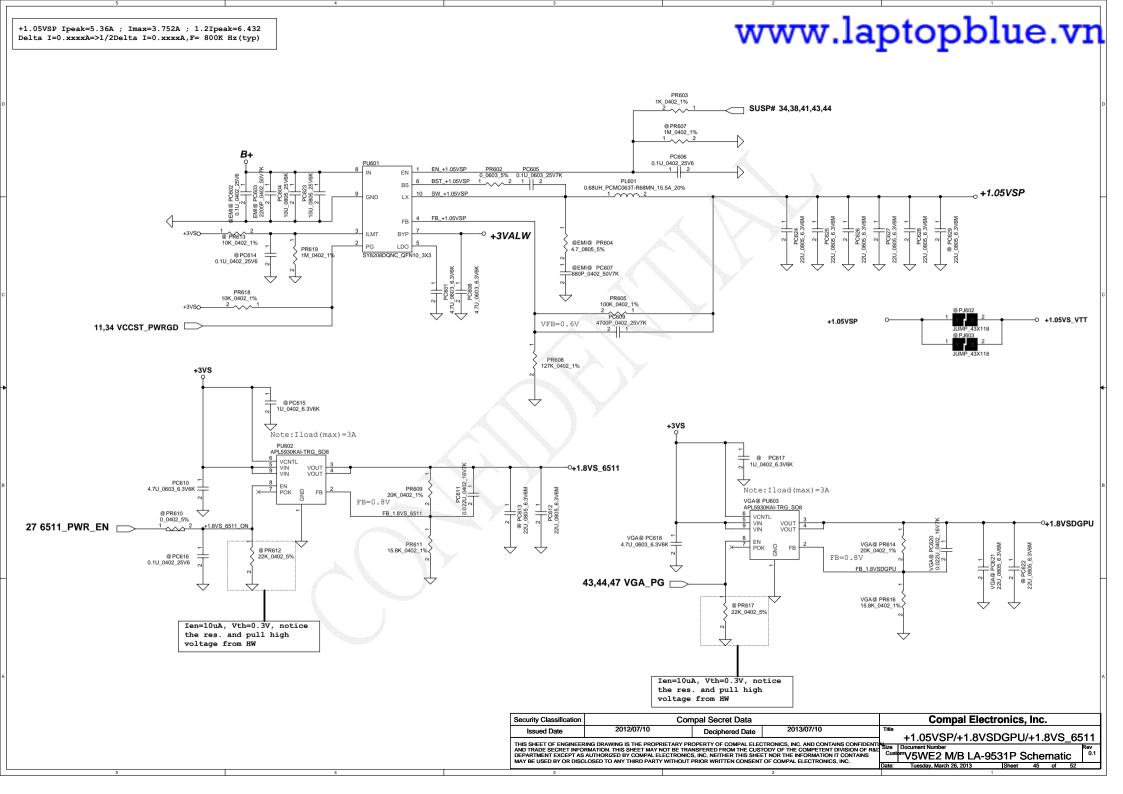


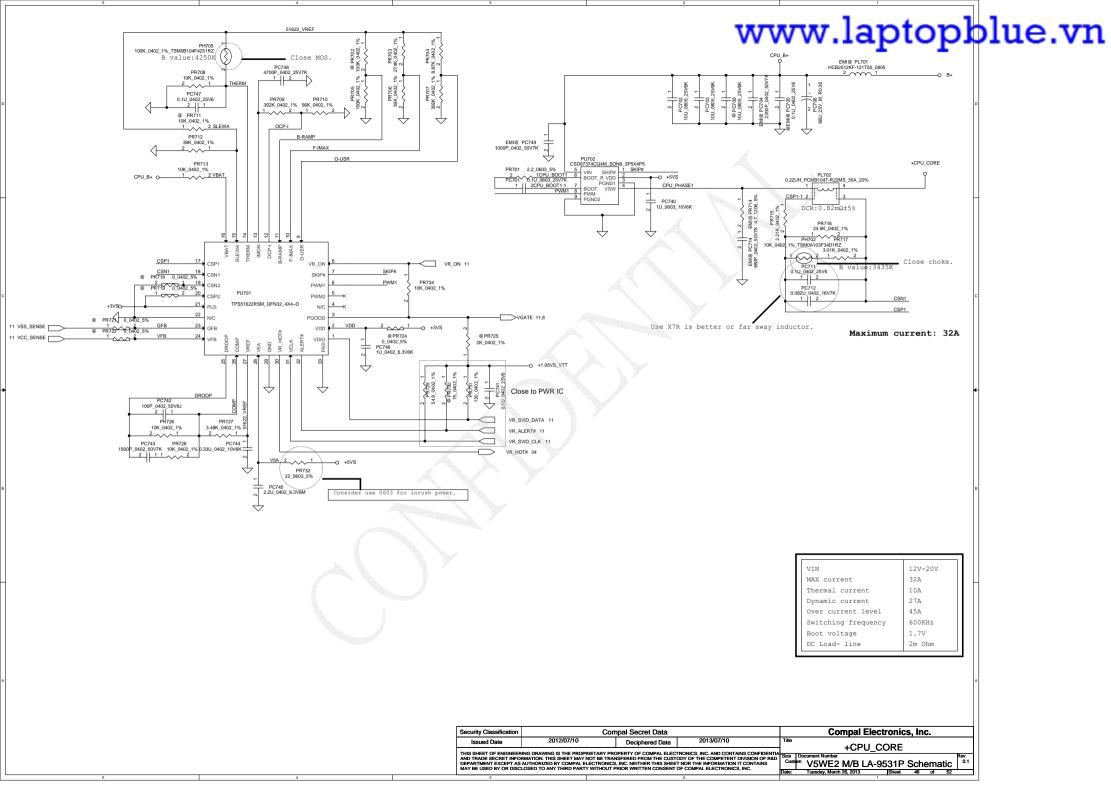


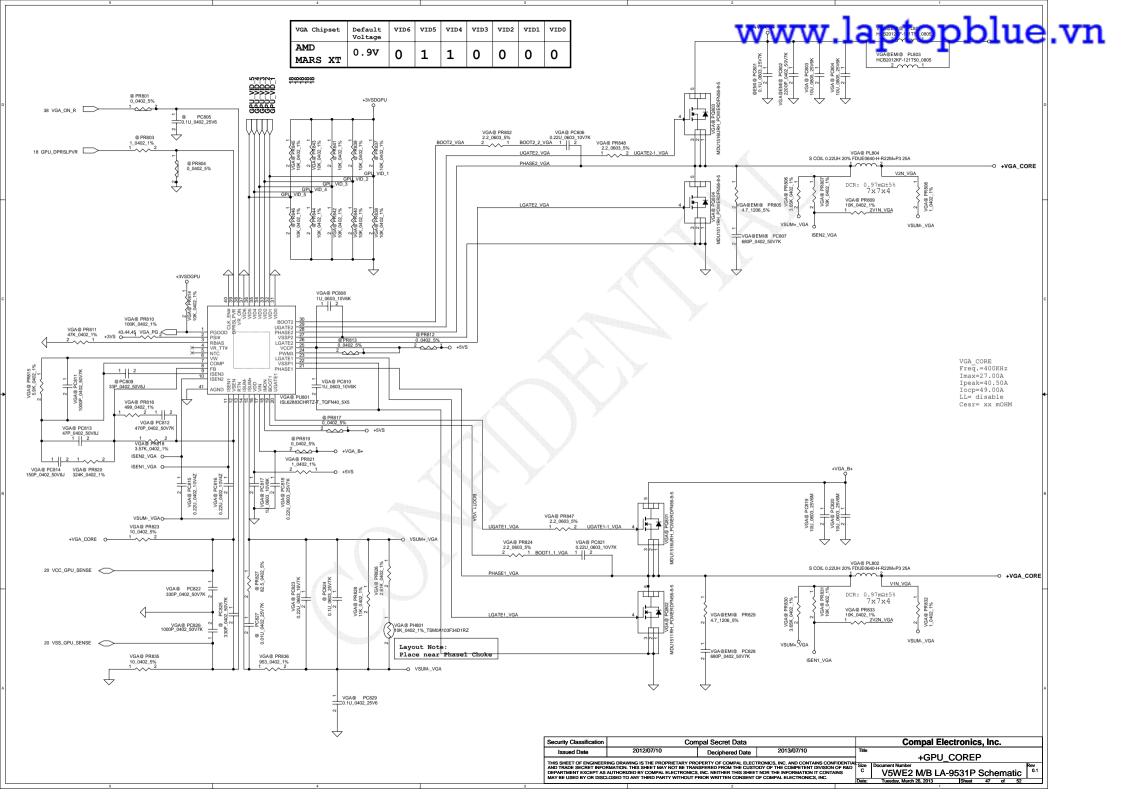


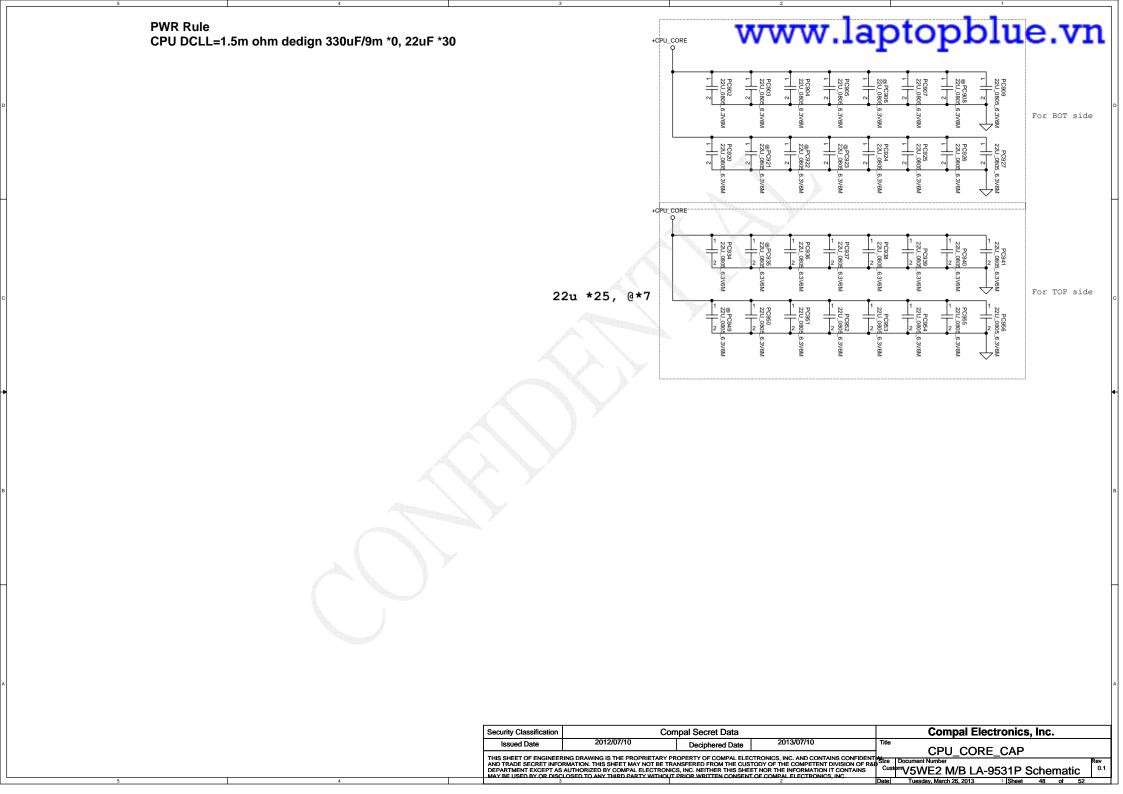


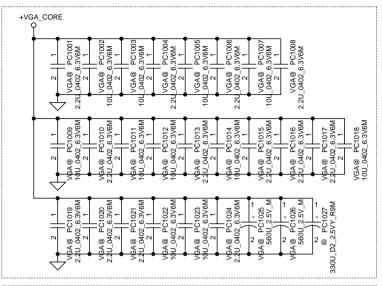




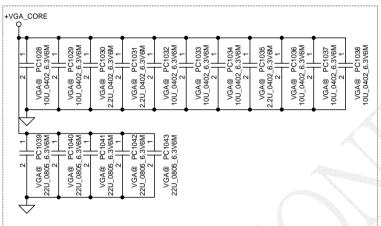








AMD MARS GPU_CORE 560uF*2+330uF*1 10uF*8+2.2uF*16



AMD MARS meet ripple 22uF*5+10uF*11

Security Classification	Con	Compal Electronics, Inc.		
Issued Date	2012/07/10	Deciphered Date	2013/07/10	VGA CORE CAP
DEPARTMENT EXCEPT AS		S, INC. NEITHER THIS SHEE	TRONICS, INC. AND CONTAINS CONFIDENT IODY OF THE COMPETENT DIVISION OF R& ET NOR THE INFORMATION IT CONTAINS OF COMPAL ELECTRONICS, INC.	Size Document Number Rev 0.1

Version change list (P.I.R. List)

Pawww.laptopblue.vn

for	PWR

Item	Fixed Issue	Reason for change	Rev.	PG#	Modify List	Date	Phase	
1	Tune VGA sequence	Tune VGA sequence		VGA	PR801 change to 20K Add PC805, PR814 Delete PR615, PC619, PR511, PC513, PR530, PR531, PC530	11/06	DVT	
2	Module Design	Module Design change 3/5V solution		3/5V		11/13	DVT	
3	3	Change RTC type to non-charge		39	Un-pop PR112, PR113	11/13		
4		Check no need keep with HW		39	Delete PR112, PR113, PBJ101	11/20	DVT	Recovery at PVT phase
5	EMI request			EMI	Add PR518, PC522, PR714, PC714, PR829, PC828, PR806, PC807, PC749 Change PR701 to 2.2	11/20		
6	EMI request	EMI confirm remove		EMI	Delete PL102, PC103, PC101, PL202, PC201 and PL703	11/26		
7	Costdown			42	Change PL402, PL403 from 5x5x3 to 7x7x3	12/13	DVT2	
8		SY8208B/C update		42	Add PR411, PR413	12/22	DVT2	
9	+1.05V ripple close upper and mean too low	Adjust output voltage and add Cff		45	Add PC609 into 4700P Change PR608 from 133K to 127K	12/22	DVT2	
10	VGA_CORE can't disable	Modify VR_ON to VGA_ON_R net		47	Change PR801 from 20K to 0 Reserve PC805	<u> </u>	DVT2	
11		Improve CPU transient character		46	Change PR709 from 150K to 390K, PR732 from 10 to 22, PC745 from 1U to 2.2U, PC711 from 0.082U to 0.1U	01/09	DVT2	
12		Improve CPU transient character		48	Unpop PC902	01/09	DVT2	
13		Tune sequence		42	Change PC428 from 4700p to 10n,	02/04		
		-		<u> </u>	PC427 from 0.047u to 6.8n			
14		0 ohm reduce			Change PR801, PR507, PR513, PR523 to R-page			
15		To meet MARS/AMD ripple SPEC		49	Add PC1028~PC1043	02/22		
16		Provide 3/5V PG signal to EC		42	Add PR416	02/22		
17	EMI request	Modify H-Gate resistor		47	Change PR847, PR848 from 0 to 2.2	02/25		
18	ESD request			39	Add PC101 into 0.1uF	02/26	··· · ······	
19	ESD request			43	Add PC521, PR503, PC507	02/26		
20		Use HW to control VCIN1 function		40	Add PR204	03/05	PVT	
21	ME issue	Shrink component to reduce Z height			Change PC303,PC304,PC315,PC318,PC517, PC819,PC820 from 0805 to 0603	03/26	PVT2	
***************************************				:		!		

Security Classification	Con	npal Secret Data		Compal Electronics, Inc.	
Issued Date	2012/07/10	Deciphered Date	2013/07/10	Title DID (DWD)	
				T PIR (PVR)	

THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENCE.

AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERED FROM THE CUSTODY OF THE COMPRETENT DIVISION OF REPORT AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERED FROM THE CUSTODY OF THE COMPRETENT DIVISION OF REPORT AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERED FROM THE CUSTODY OF THE COMPRETENT DIVISION OF REPORT AND THE CUSTODY OF THE COMPRETENT DIVISION OF REPORT AND THE CUSTODY OF THE COMPRETENT DIVISION OF REPORT AND THE CUSTODY OF THE COMPRETENT DIVISION OF REPORT AND THE CUSTODY OF THE COMPRETENT DIVISION OF REPORT AND THE CUSTODY OF THE COMPRETENT DIVISION OF REPORT AND THE CUSTODY OF THE C

A --> B1 Change List 1.Delete +3VALW to +3VALW PCH MOS Circuit: Page12, Delete C589,C414,R77,O10,C590,C591 Page34, Delete U28.16 PCH_PWR_EN# off page 2.Page12, Unpop R210 ,Pop L3 and C22 for +1.05VS_VTT high ripple 3.Unpop and Componment reduce-----1.Page11, R169 change to @ 2.Page36, Mound R417 (Cancel AMIC@) Page16, Delete C824,C828,C831,C836,C839 for unpop reduce. 3.Page18, R898, R899, R409, D22 change BOM Structure to VGA@ Page20, Delete C870, C871, C923, C922, C921, C920 for unpop reduce. 4.Page34, R485, R483 change to 9012@ Page27, Change R399,L30,L47 TO R_Short R310.1 change to +3VS R479, R478 change to 940@ Delete C456, C637, C474, C497, C580, C581
Pop R80 and unpop R396, Q25, C411, R584, Q52
Page28, Delete C606, C646, C607
Change R239 to R_short
Page29, Delete C775, C776, C778, C781, C782 5.Page35, C663, SW4, SW5 change to 9012@ 5. Change all 9320 to 9400 6.Page19, Delete R1035, X7601/X7603/X7604 7.Page17, R1006 change to VGA@ 8.Page09, R306 add BOM structure UMA@ 6. Page11, R169 change to XDP@ 9.Page06, C153, C154 change to 15P 0402 Page31, Delete C461,C462 7. Page12, add C414 and change PCH PWR EN to PCH PWR EN# 10. Page18, C848, C849 change to 12P 0402 delete Q33, R561, R563 8. Page16, delete R58, R298, R300, C163, R299, R302 Change R423 to R short 11.Page07, C2, C3 change to 10P 0402 Page32, Delete C161 0. Fage17, Add option component (U51) for SUN XT 10. Page19, Add R900, R901 with BOM structure @ 11. Page24, delete R405, U20, R362, R401, C164 Change U8 to G5243AT11U(SA000028Y10) Change R308 to R_short 1.Page32, JODD1.11 Reserve a TestPoint for DFT Page34, Change R495 to R_short Page36, Chagne L55,L54,L52 to R_short 2.Page29, Pop C779, C783 3.Page17, Update U51 BOM Structure for BOM Select 4.Page24, SWAP RP41.1,RP41.2 4.Page04, Add QDJC@ BOM Structure for U1 12. Page25, delete R367, D7, F1, D8, D19 5.Page27, Change R123,R127 Pull high to +HDMI 5V OUT 13. Page26, change L47, L48 to BLM18AG121SN1D(SM010030010)
14. Page27, Delete D31, F2, C450 1.Page18, Add D22 to prevent GPU ACIN leakage 1. Page22, Add X7603@ for VRAM 2Gb*4 HYN 128M16 2.Broadcom recommend modify (Add componment Function Field is 45.1)
Page29, Add C803 0.1uF to U48.20(VDDO CR), Add X7604@ for VRAM 2Gb*8 HYN 128M16 15. Page28, Delete R781, D23, R782, R785, U49, C803 13. rage20, Delete R732 change T1 to GST5009-E (SP050006B10) 17. Page30, delete R414, C166 R438, Q20 change to @ Page29, Add L74(BLM31PG601SN1) between Q6.1 and +3V_LAN 1. Page06, Add R937 for EC SCI# Path to GPIO34 Add C820 (1uF) to Q6.1 Page30, Add L75(BLM31PG601SN1) between Q9.1 and 2. Page09, RP28.5 connect to GPIO34 +XDPWR_SDPWR MSPWR Change U9 to G5243AT11U(SA000028Y10) with BOM@ 18. Page31, delete R595, R587, Q34, R597, R596, R562 1. Page06, Delete chargeable RTC circuit Add C820 (1uF) to 09.1 Change ODD to SATA port1 3.Page18, Change L69 to R Short Change JUSB1 to OCTEK USB-09EAAB(DC233008020)
Delete R472, R469, R460, R462, C635, U46, R459, R463, R464

20. Page33, Mount R503 Page 32, Modify ODD SATA netname to SATA port 1 . 4.Page20, Change L72 to BLM18AG121SN1D (the same to L71) 5.SW confirmed function 2. Page29, +1.2V_LAN_OUT add 680P for EMI 3. Page37, Modify H2 $\overline{1}$ from 2P5 to 3P0 4. Page38, Add 2 jump for power cousumption measure Page08, unpop R245,d21 (ACPRESENT tp PCH no need) Page36, unpop R529 (
6.Default EC SCI# to GPIO34 (EC BEEP no need) Change R506 to 8.2K J36(+3VS), J37(+5VS) Change R509 to R Short with BOM @ Page06, Pop R937 5. Delete XDP port and related circuit Delete R491, R493, D20 Page09, Unpop R66 Page04, Delete C63,C64,C96,C97,C98,R20,R21,R22,R23,R27~R31 21. Page34, add R535 (100K 0402) 7.Reserve DGPU_HOLD_RST# direct to PLTRST_VGA# path Page08, Add R405 Oohm connect DGPU_HOLD_RST# and PLTRST_VGA# Delete R3, R86, R87, R88, R89, R90, R91, R4, C92, C93 Mount R632 21. Page35, L51 change to BLM18AG121SN1D(SM010030010) Change JM1C1 to ACES_88266-02001(SP020008Y00) Delete R5,R14,R15,R16,R7,R19,R25,C35,JXDP1 3.Page35, Chagne R702 to 680ohm (ME confirm) Page07, Delete R66,R67 9.Page35, Delete SW1 (debug) for Layout convenience Delete R143, R668, R162, R181, C719, R671 6. ESD DVT Modify: 10.Page24, Change L6 to (4.7uH_SH00000GS00) same as Q5WV8 11.Page29, Change RP22 to R768, R769, R770.R771 for SD 3.0 EMI 23. Page37, delete R424, C169
Change U12 to G5243AT11U(SA000028Y10) Page08, Delete C39 Page24, Delete D6 Page28, Delete D7, D18 24. Page43, SW1 change BOM Structure to @ 1.Page24, Change U50.11 connect from L6.2 to L6.1 Page30, Delete D38 2.Page34, Change R502 from R short to 940@ Oohm Page33, Delete D16 1. Modify BOM Structure/Function Field for EMC@(45.1) 3.Page36, Change R237,R238 to 60 Ohm (Codec vendor recommend) Page35, Delete D25, D30, D34 4.Page09, Add R67 for EC SCI# -> GPIO 10 option Page07, RP19, R390 Page36, Delete D26,R544,C572 Page37, Delete ESD TP JUMPs: Page24, L11 .Page36, Delete D26 (ESD Confirm) J10, J20, J17, J21, J16, J19, J18 J22, J24, J28, J25, J29, J23, J27 Page25, R368, R369, R370, R371, R372, R373, R374, R375 2.EMI part Schematics modify(EMI confirm1123) Page27, L42, L45, L46,R175, R180 Page26, Change R368,R369,R370,R371,R372,R373,R374,R375 to 0403 J26, J30, J31, J33, J32, J34, J35 Page29, C786 change to EMC@ Page29, R897, C814, D39 Page28, Change R175,R180 to 0603 R short Page04, Add C96 to DIMM DRAMRST# Page32, L24, L25, R458, R461 Page36, Change L36, L38, L51, R527, R528, R532, R533 to 0603 R short Page33, C487 change to EMC@ and 0.1uf Page35, R527, R528, R532, R533, L36, L38, D1, C62 Page32, Delete C408,C398 Delete D4
Page26, C378 change to EMC@
C387 change to EMC@ Modify BOM Structure/Function Field for XEMC@(45.1) Page04, C63, C64, C96, C97, C98, C94, C95, C60, C92, C93, C35 Page07, R104, C152, R402, C453 Page33, Delete R453,R455,R456,R457 3.Page38, Change 3/5 VS circut BOM Structer to 35V@ 4.Page32, Modfiy JHDD1 to LTCX004LGA0 (S H-CONN CCM C127043HR022M27FZR 22P H3.05 HDD) Page08, C39 1. Page06, Add a nochargeable RTC battery. Page24, C528, C549, C364, C365, D6 Modfiy JODD1 to LTCX004HZ00 (S H-CONN SANTA 20190X-X 13P Page15, Add R191 for DDR_VTT_PG_CTRL pull high +5VS option. Add page24, Reserve eDP to LVDS translator (RTD2132R) Page25, D2, L13, L14, L15, L16 Page28, C792, C786 Add bom structure TL@(translate) and EDP@(eDP mode)
4. Page25, Add R947 for ENVDD option.
Add connect TL_INVT PW to INVTPWM
Add connect RTD2132R TL_HPD to EDP_HPD Page29, R26, C26, C806, C807, C808, C809, JP1, JP2, D38 Page31, C408, C398
Page32, D15, D16, D4, C487, R453,R455, R456, R457, L26
Page33, R477, C501, R513, C520, C506, C507, C511
Page34, C551, C553, D25, D30, D34 Modify JLVDS1 pin net name fo Co-Lay eDP & LVDS Page35, R548, C573, R671, C719, C556, C550, C444, C445, D27, D37, D26, R544, C572 Modify Function Field to 45.1 only (BOM Structure is same as before) Page04, R27, R28, R29, R30, R31 Page33, R160 Page35, R143, L51 4. Display BOM structure and Value of U1 (CPU) 5. Display BOM structure of R0402 OOHM-NEW and R0603 OOHM-NEW (R Short Pad show BOM Structure @) 6. Page08, Update note of GPIO66

Security Classification	Cor	npal Secret Data	Compal Electronics, Inc.	
Issued Date	2012/07/10	Deciphered Date	2013/07/10	Title PIR-HW1
THIS SHEET OF ENGINEER	RING DRAWING IS THE PROPRIETARY F	ROPERTY OF COMPAL ELE	ECTRONICS, INC. AND CONTAINS CONFIDE STODY OF THE COMPETENT DIVISION OF	FIR-FIVVI
DEPARTMENT EXCEPT AS	AUTHORIZED BY COMPAL ELECTRON	CS, INC. NEITHER THIS SHI	EET NOR THE INFORMATION IT CONTAINS	Custom V5WE2 M/B LA-9531P Schematic 1.0

B1 --> B2 Change List

0114-----

```
1.Page03, Add U1 with QDJA0
2.Page30, R897 change to SM01000LU00
3.Page24, L63,L73 change to SM01000EJ00
4.Page25, L11 change to SM01000EJ00
5.Page36, L33 change to SM01000EJ00
6.Page31, U9, C165 with IOAC@
0110-----
1.Page32, Delete R312,R313,R314,R315
            Add C392,C393,C391,C394 with EA500
2.Page27, Add C35
3.Page38, Delete Q45,R570,R571
1. Page33, R458, R461 change to R0402 00HM-NEW
            Add JFP1
2. Page26, Delete L13, L14, L15, L16
3. Page29, Delete C792, C99
4. Page31, Delete J4
5. Page10,25 change Touch screen port from USB port 5 to port6.
6. Page25,34 change net name of TS INT to TS EN
7. Page10 add USB port 5 for Finger Print
8. Page38, Add C19
9. Page26, Add C396, C398
10.Page36, Mount C554
11.Page38, Mount C979
12.Page35, Reserved SW6,SW7,SW8,SW9
13.Page32, Add C534, C535, C536, C537 for JHDD2 with BA510
            change C391, C392, C393, C394 to R312, R313, R314, R315
Update Power schematics
0107-----
3. Page08, R62, R65 change to 0402 00HM-NEW
4. Page10, Change Touch Screen USB port frum Port3 to Port5.
R155 change to R0603_00HM-NEW

5. Page24, Change Q53 to @

6. Page25, R947,R363,R949 change to R0402_00HM-NEW
            Add C376, C377, C388, C389 with TL0
            Add R414, R426
            Add R424, R425 with @
7. Page27, R80 change to R0603_00HM-NEW L48 change to R0603_00HM-NEW
8. Page29, C99 change to XEMC@
R774 change to 56_0402_5%

9. Page32, R49, R593 change to R0805_00HM-NEW

9. Page34, R236 change to R0805_00HM-NEW
10. Page38, R926 change to R0402 00HM-NEW
1.Page35, R698,R701 change to 680 ohm
R702 change to 499 ohm
2.Page18, Un-mount C847
3.Page38, Add U38, R77, C63
Update Power Schematics
1. Page25, Add USB20_P3/N3 on JLVDS1.35/36
            Add R81
2. Page35, Delete JTP1, R609, R610, C552, R693, R607, R608, D36
3. Page34, change Q50 to L2N7002LT1G SOT23-3 change R506 to 18K 0402 5%
```

B2 --> C Change List

1.Page27,	Mount R410, R411
	Change R240, R241 with @
	Change R418 to 4.7K
	Mount C872, C873, C874, C889, C917, C918, C919
	change C371, C372, C369, C370 with EDP@
	Change L24, L25 to SM070001E00
2.Page12,	
3.Page34,	
J.1490J1,	Reserved D26
0227	
1.Page29,	
	change JDB1 to E-T 1001K-F50C-05R 50P-S
Modify fo	r ESD
	Mount C13, C14 (10U_0603)
1.Page12,	Change C40 to 10U_0603
	Mount C31 (1U_0402)
3.Page15,	Mount C117 (10U_0603)
	Add C161 10U_0603
4.Page33,	Mount C483 with 0.1U
E D20	Reserved D3 with XEMC@
	Add C39, C64,C92,C93 22U_0805 wer schematics
0226	
1.Page12,	
	Mount R204, R241, R407, R408
,	Change R412,R413 with @
3.Page28,	Add R312 with 0
4.Page34,	Del R590 (Add offpage for H_PROCHOT#_EC)
	Del R505
	wer Schematics
	R898, R899 change to R0402_OOHM-NEW
2.Page25,	Add TS@ for R81, R414, R426
0210	
	34,37 G SEN INT connecto to PCH GPIO80
1.1age00,	Change U2.4, U2.6 to D CK SCLK/D CK SDATA
2. Page 29.	Reserved C815
	Add C1024, C1025, C1026, C1023, C1027, C1028, C1029, C1030 with 128@
4.Page23,	Add C1031, C1032, C1033, C1034, C1038, C1036, C1037, C1035 with VGA@
	Reserved R556, R574, Q55, R557, R575, Q41, R570, R571, Q45
0218	
1.Page06,	Update Y1 CIS Symbol
	Add D23, C151
	Change R446, D32, C168 to 0
	Change C823, C827, U52, R798 with @
	Add R781, C792
	Add R782 and Mount C822
∠.Page34,	Change R506 to 33K

C --> Pre-MP Change List Compone Ville VIII

2. Page06, unmount R446, C168, D32 Mount D23, C151 0329-----

1.Page04, Add SR16Q@ and SR170@ for U1 2.Page06, Change C151, D23 with @ Mount R446, D32, C168 1.Page1, Change PCB PN to DA60000XL10 2.Page29, Mount C815

0321-----1.Page8, G_SEN_INT change from GPIO80 to GPIO52. 2.Page34, change R506 to 100K 0402 5%

Update Power Schematics

Security Classification	Con	npal Secret Data			Compal Electronics, Inc.
Issued Date	2012/07/10	Deciphered Date	2013/07/10	Title	PIR-HW1
THIS SHEET OF ENGINEER	RING DRAWING IS THE PROPRIETARY P	ROPERTY OF COMPAL ELE	ECTRONICS, INC. AND CONTAINS CONFIDE STODY OF THE COMPETENT DIVISION OF I	Size I	Document Number Rev
DEPARTMENT EXCEPT AS		CS, INC. NEITHER THIS SHI	EET NOR THE INFORMATION IT CONTAINS	Custon	V5WE2 M/B LA-9531P Schematic 1.0

Friday, April 26, 2013